

### Product Description

Qorvo's QPA1011 is a X-band high power MMIC amplifier fabricated on Qorvo's production 0.15um GaN on SiC process (QGaN15). The QPA1011 operates from 7.9 – 11 GHz and typically provides 25 W saturated output power with power-added efficiency of 37.5% and large-signal gain of 19.5 dB. This combination of wideband performance provides the flexibility designers are looking for to improve system performance while reducing size and cost.

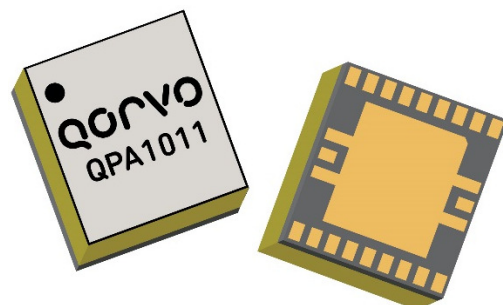
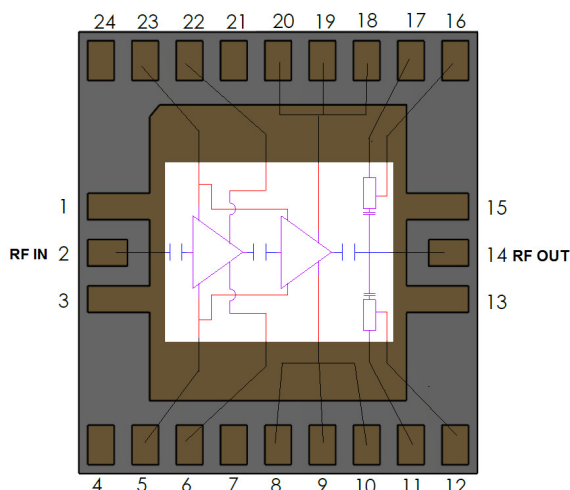
QPA1011 can also support a variety of operating conditions to best support system requirements. With good thermal properties, it can support a range of bias voltages and will perform well under both CW and pulse operations.

The QPA1011 is matched to 50Ω with integrated DC blocking capacitors on both RF I/O ports simplifying system integration. The wideband performance and operational flexibility allows it support satellite communication and data links, as well as, military and commercial radar systems.

Lead-free and RoHS compliant.

Evaluation boards are available upon request.

### Functional Block Diagram



### Product Features

- Frequency Range: 7.9–11 GHz
- $P_{OUT}$ : 44.5 dBm at  $P_{IN} = 25$  dBm
- PAE: 37.5 % at  $P_{IN} = 25$  dBm
- Large Signal Gain: 19.5 dB at  $P_{IN} = 25$  dBm
- Small Signal Gain: 26 dB
- Integrated Power Detector
- Bias:  $V_D = 24$  V,  $I_{DQ} = 1200$  mA,  $V_G = -1.9$  V Typical
- Pulsed  $V_D$ : PW = 100  $\mu$ S, DC = 10%
- Package Dimensions: 4.5 x 5.0 x 1.72 mm

*Performance is typical across frequency. Please reference electrical specification table and data plots for more details.*

### Applications

- Satellite Communications
- Data Links
- Military and Commercial Radar

### Ordering Information

| Part No. | ECCN          | Description                           |
|----------|---------------|---------------------------------------|
| QPA1011  | 3A001.b.2.b.2 | 7.9 – 11 GHz 25 W GaN Power Amplifier |

## Absolute Maximum Ratings

| Parameter                                                                  | Value / Range     |
|----------------------------------------------------------------------------|-------------------|
| Drain Voltage ( $V_D$ )                                                    | 29.5 V            |
| Gate Voltage Range ( $V_G$ )                                               | –8 to 0V          |
| Drain Current ( $I_{D1}/I_{D2}$ )                                          | 672 mA / 2880 mA  |
| Gate Current ( $I_G$ )                                                     | See chart, pg. 21 |
| Power Dissipation ( $P_{DISS}$ ), 85 °C, CW                                | 70 W              |
| Input Power ( $P_{IN}$ ), CW, 50Ω, $V_D=28$ V, $I_{DQ}=1200$ mA, 85 °C     | 30 dBm            |
| Input Power ( $P_{IN}$ ), CW, VSWR 3:1, $V_D=28$ V, $I_{DQ}=1200$ mA 85 °C | 30 dBm            |
| Channel Temperature ( $T_{CH}$ )                                           | 275 °C            |
| Mounting Temperature (30 seconds)                                          | 260 °C            |
| Storage Temperature                                                        | –55 to 150 °C     |

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

## Electrical Specifications

| Parameter                                                                        |                                 | Min | Typ                     | Max | Units             |
|----------------------------------------------------------------------------------|---------------------------------|-----|-------------------------|-----|-------------------|
| Operational Frequency Range                                                      |                                 | 7.9 |                         | 11  | GHz               |
| Output Power ( $P_{IN} = 25$ dBm)                                                | 7.9 GHz<br>9.0 GHz<br>11.0 GHz  |     | 44.2<br>45.0<br>44.8    |     | dBm<br>dBm<br>dBm |
| Power Added Efficiency ( $P_{IN} = 25$ dBm)                                      | 7.9 GHz<br>9.0 GHz<br>11.0 GHz  |     | 35.6<br>38.7<br>39.4    |     | %<br>%<br>%       |
| 3 <sup>rd</sup> Order Intermodulation Level<br>( $P_{OUT}/\text{Tone} = 38$ dBm) | 7.9 GHz<br>10.0 GHz<br>11.0 GHz |     | –20.0<br>–21.2<br>–21.5 |     | dBc<br>dBc<br>dBc |
| Small Signal Gain                                                                | 7.9 GHz<br>9.0 GHz<br>11.0 GHz  |     | 29.0<br>28.8<br>28.0    |     | dB<br>dB<br>dB    |
| Input Return Loss                                                                | 7.9 GHz<br>9.0 GHz<br>11.0 GHz  |     | 13.5<br>30.0<br>17.5    |     | dB<br>dB<br>dB    |
| Output Return Loss                                                               | 7.9 GHz<br>9.0 GHz<br>11.0 GHz  |     | 9.0<br>10.0<br>16.0     |     | dB<br>dB<br>dB    |
| Output Power Temperature Coefficient (25–85 °C)<br>( $P_{IN} = 25$ dBm)          |                                 |     | –0.006                  |     | dB/°C             |
| Small Signal Gain Temperature Coefficient (25–85 °C)                             |                                 |     | –0.053                  |     | dB/°C             |
| Recommended Voltage Operations                                                   |                                 |     | 24                      | 28  | V                 |

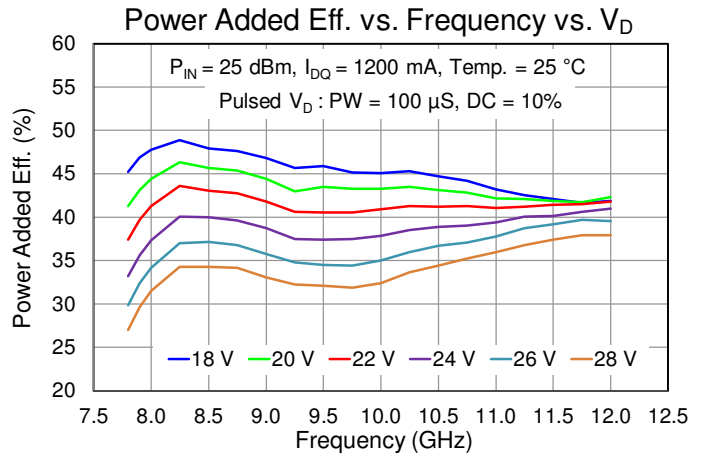
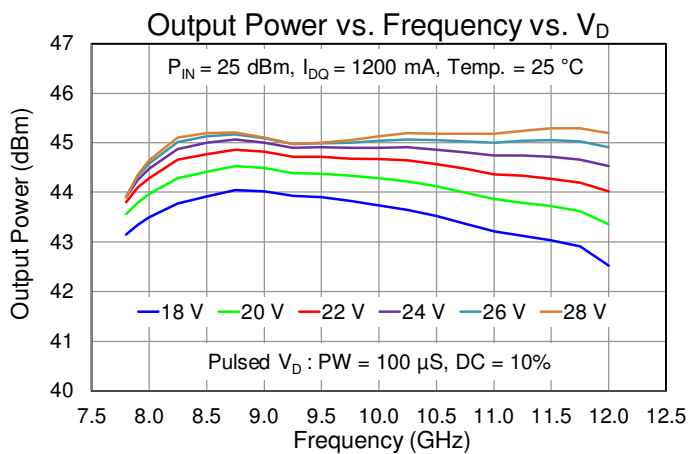
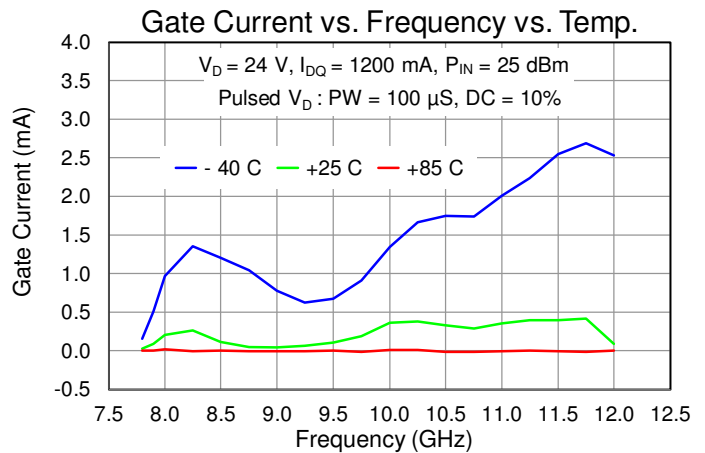
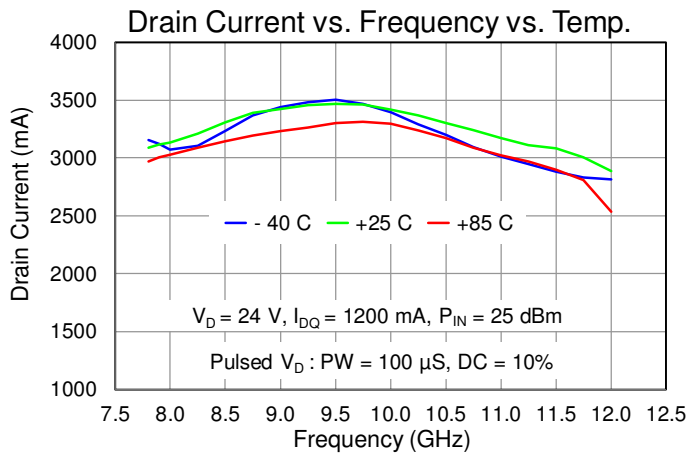
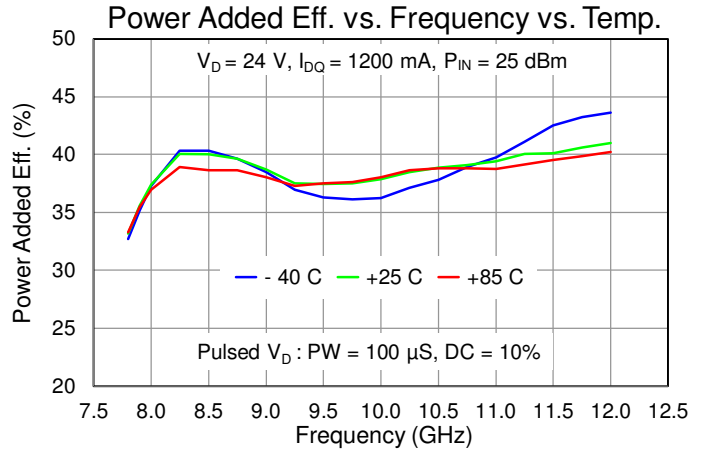
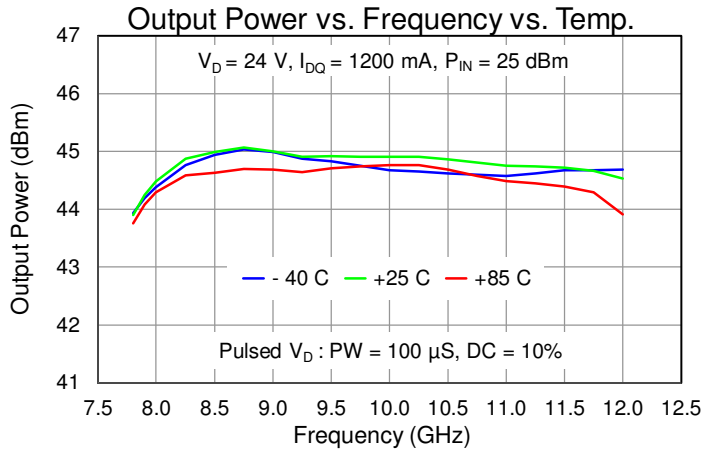
Test conditions, unless otherwise noted: 25 °C, Pulsed  $V_D$ : PW = 100 μS, DC = 10%,  $V_D = 24$  V,  $I_{DQ} = 1200$  mA,  $V_G = -1.9$  V Typical

## Recommended Operating Conditions

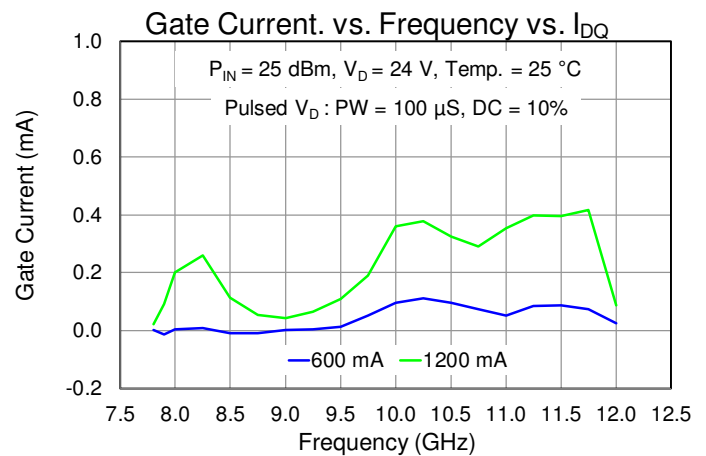
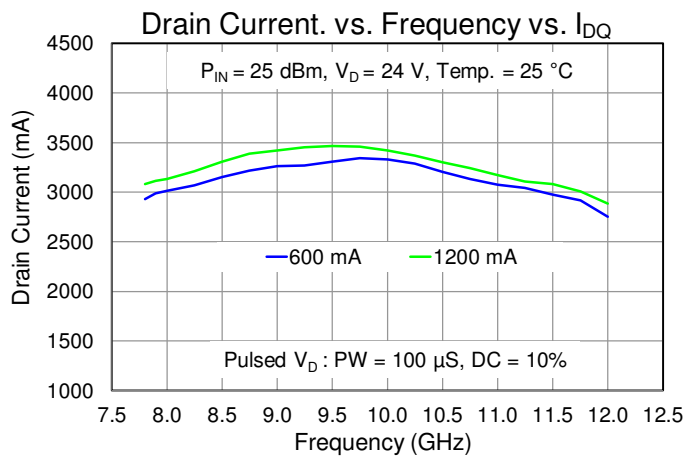
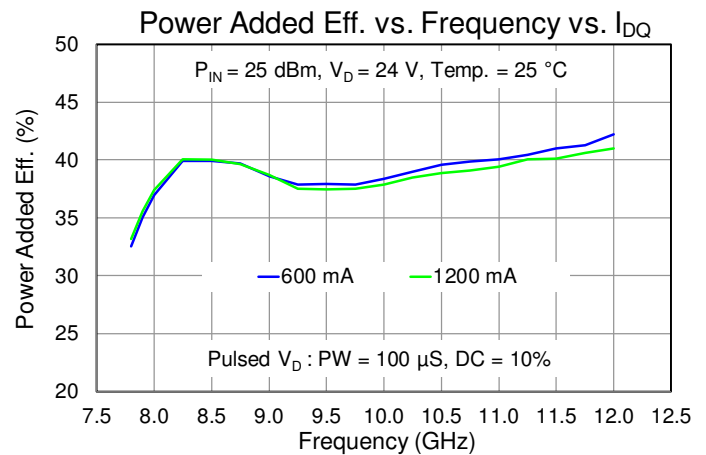
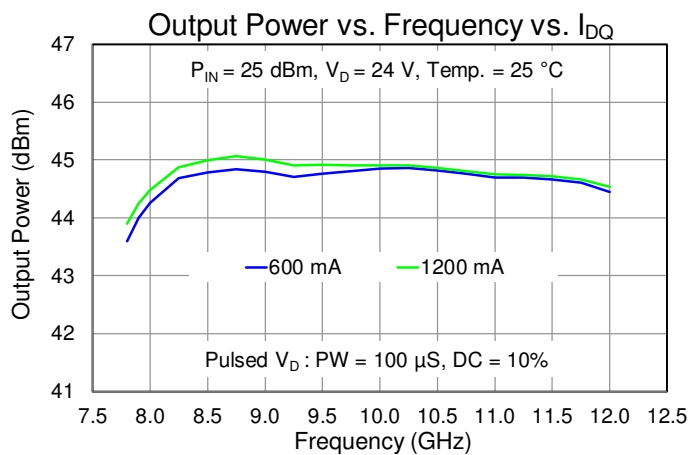
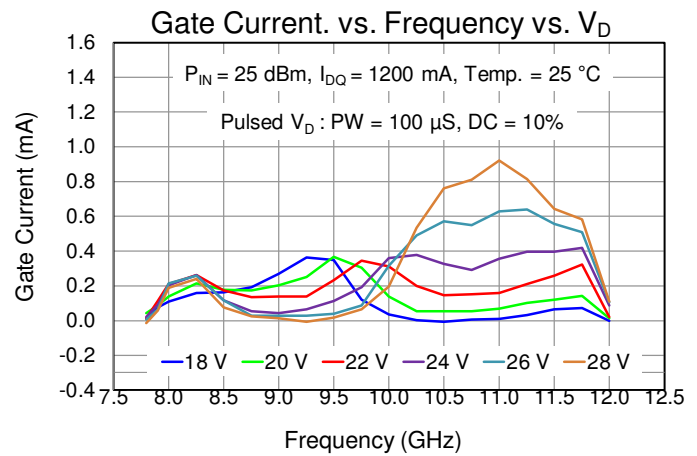
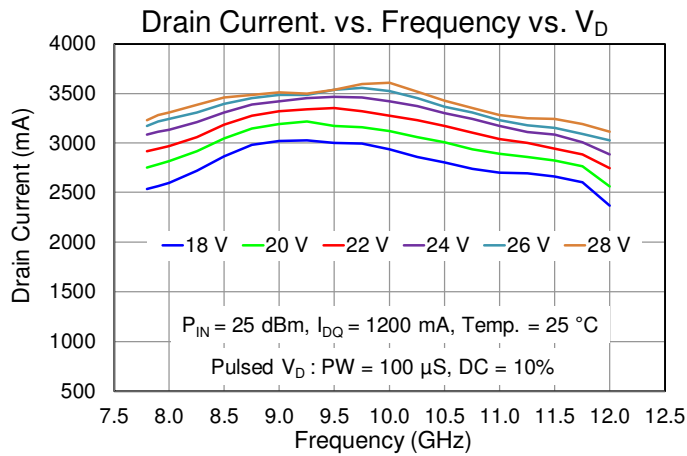
| Parameter                       | Value / Range |
|---------------------------------|---------------|
| Drain Voltage ( $V_D$ )         | 24 V          |
| Drain Current ( $I_{DQ}$ )      | 1200 mA       |
| Gate Voltage ( $V_G$ ), Typical | –1.9 V        |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

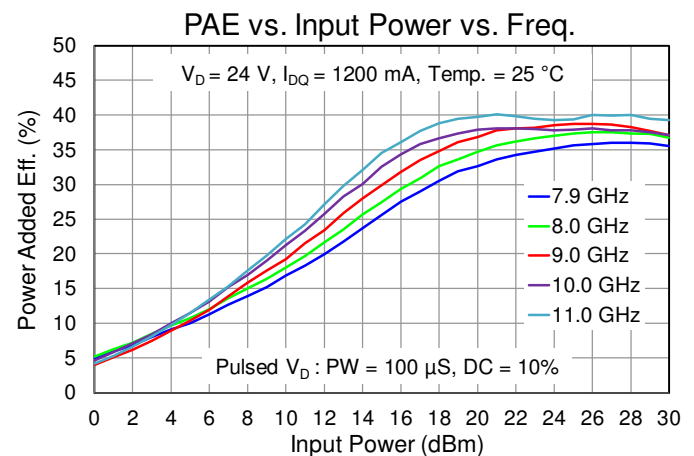
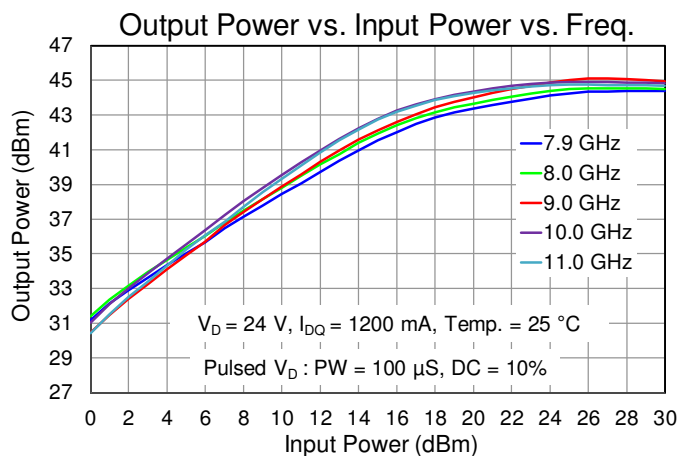
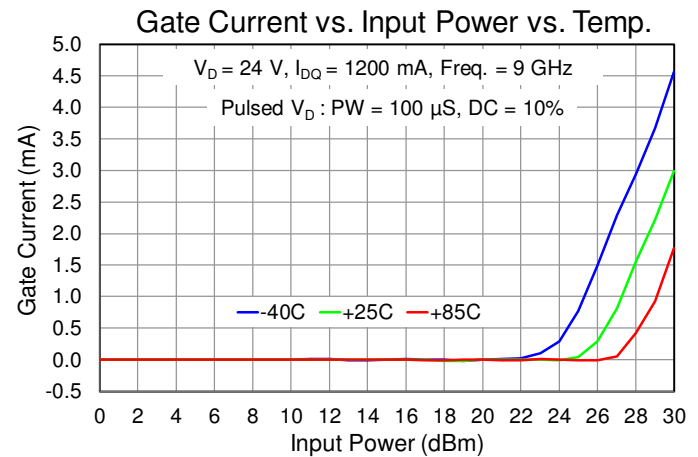
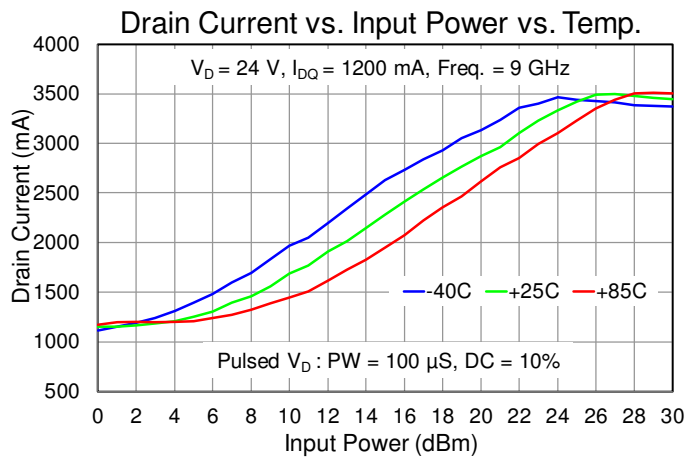
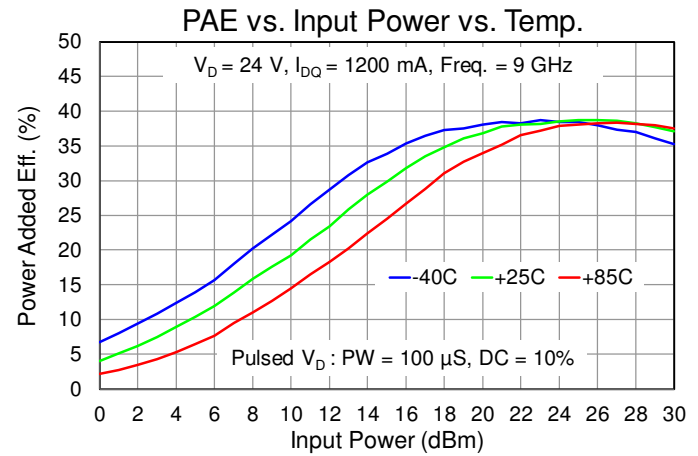
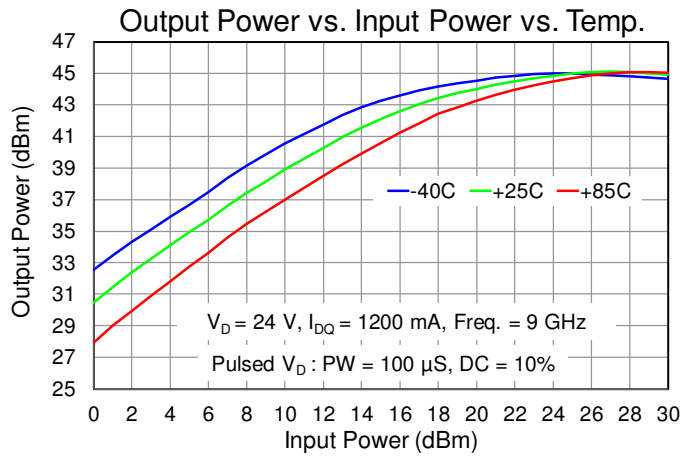
## Performance Plots – Large Signal (Pulsed)



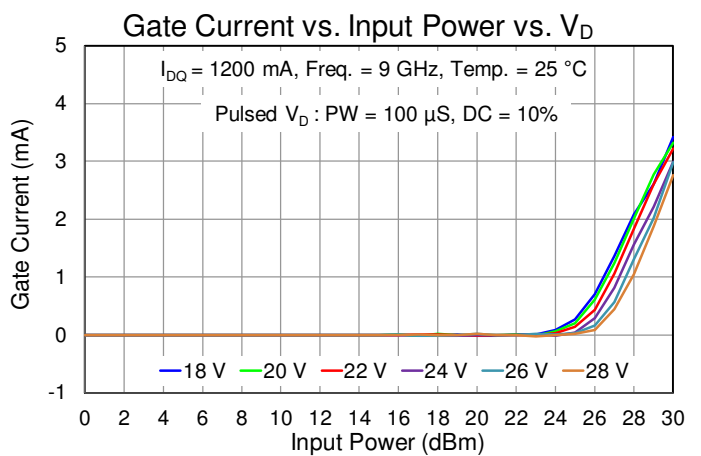
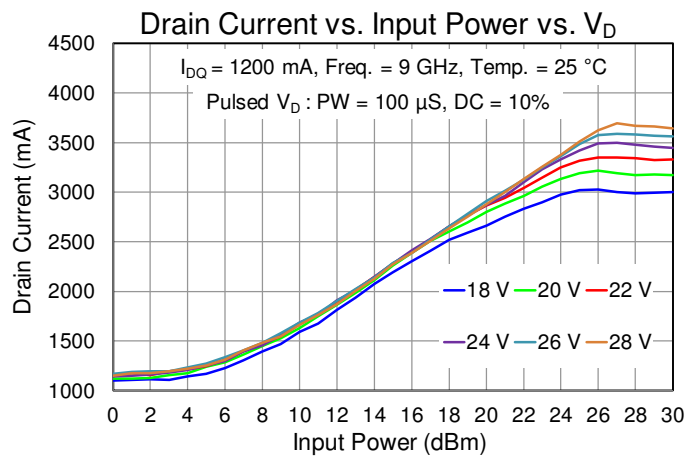
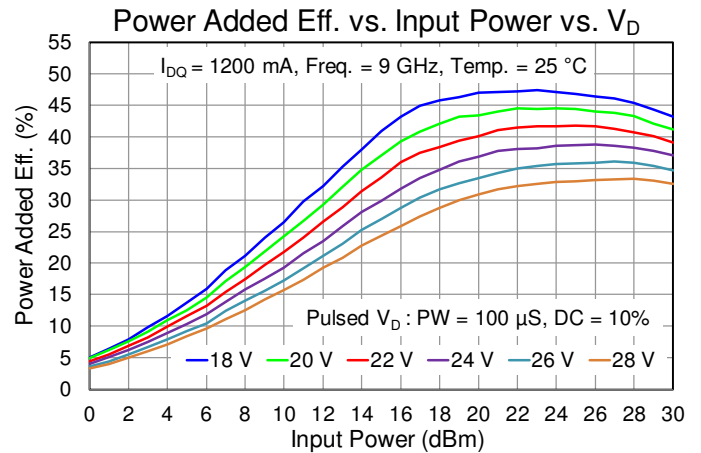
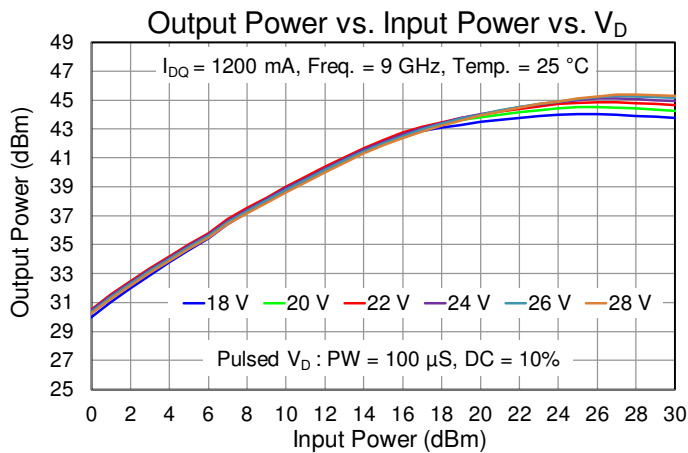
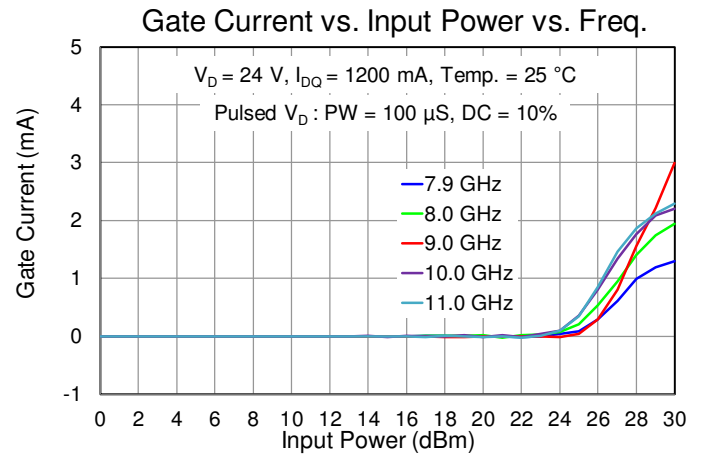
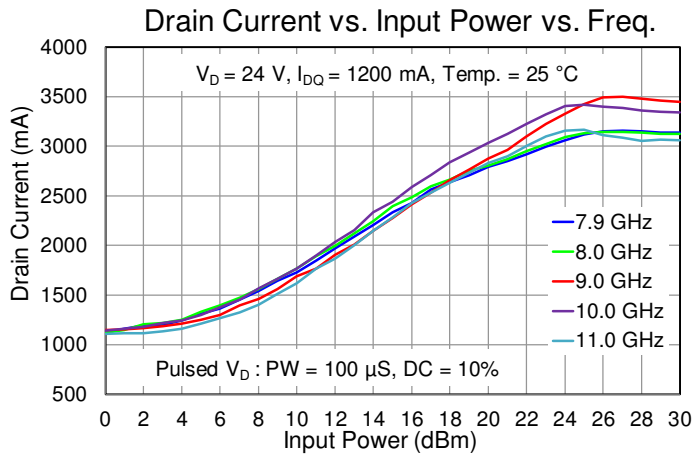
## Performance Plots – Large Signal (Pulsed)



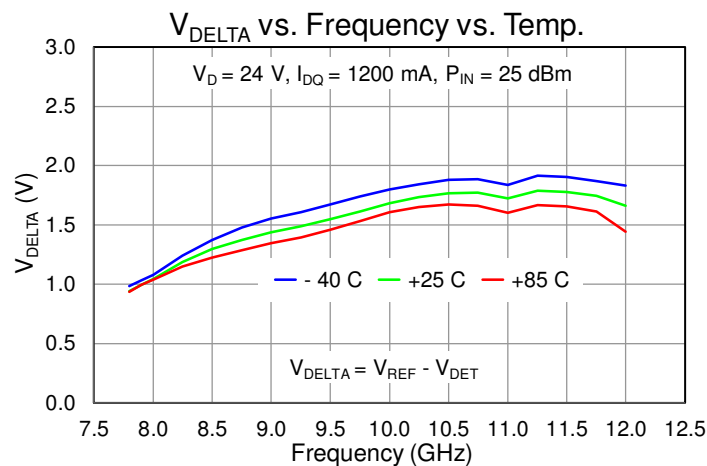
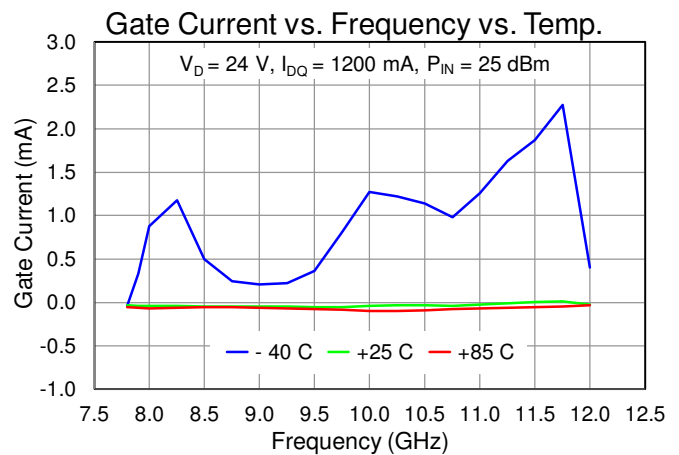
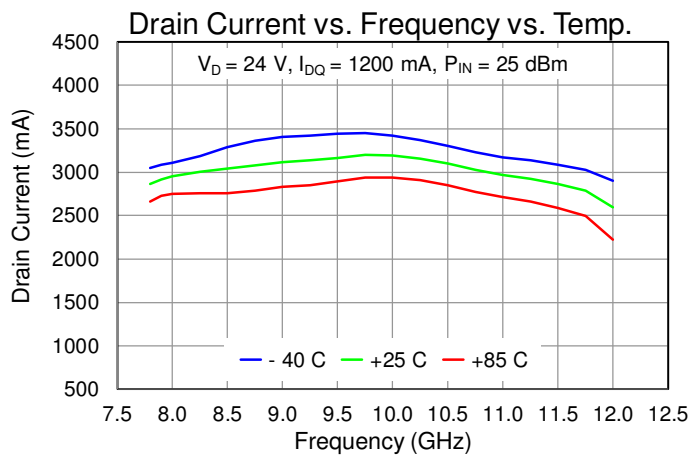
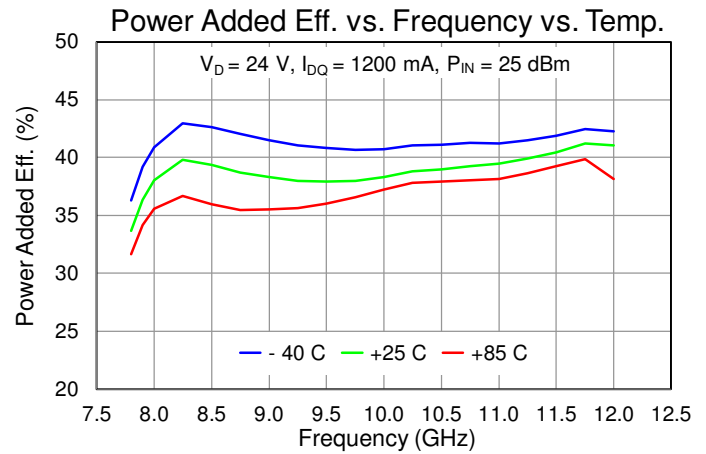
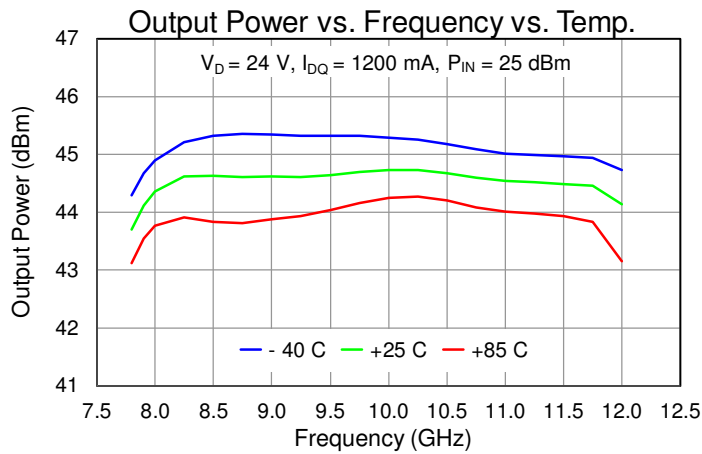
## Performance Plots – Large Signal (Pulsed)



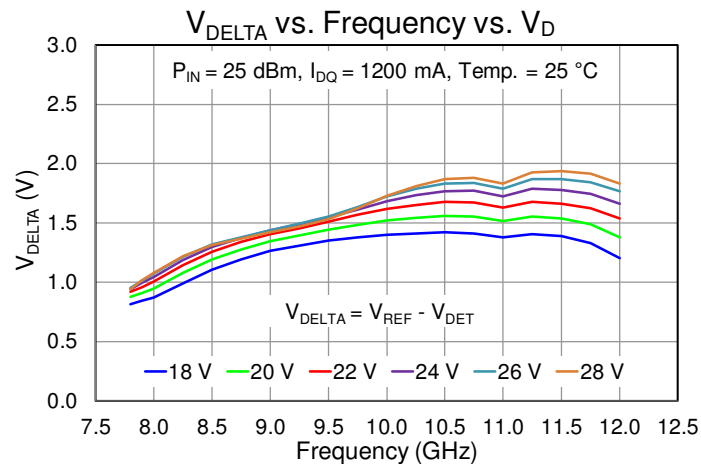
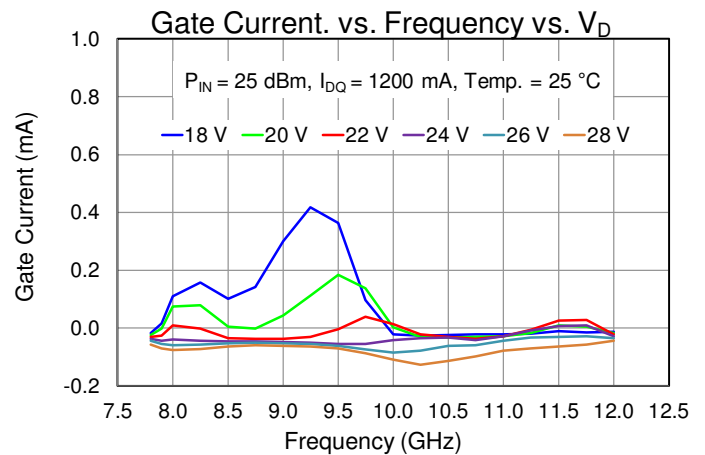
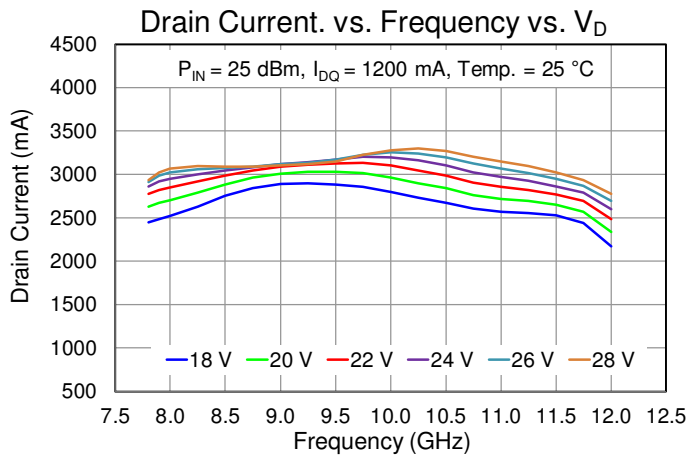
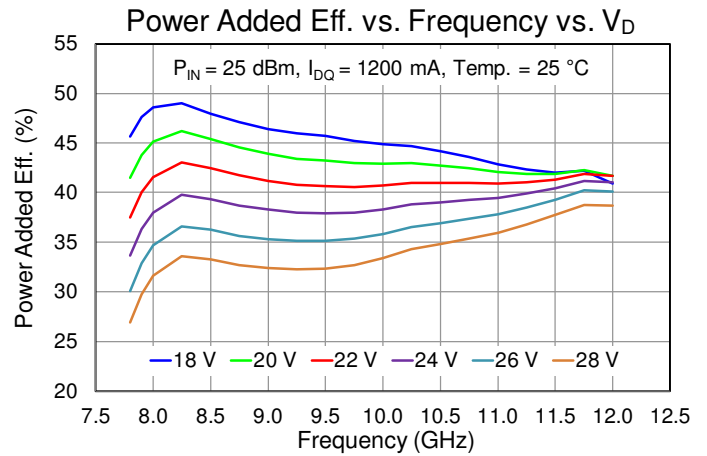
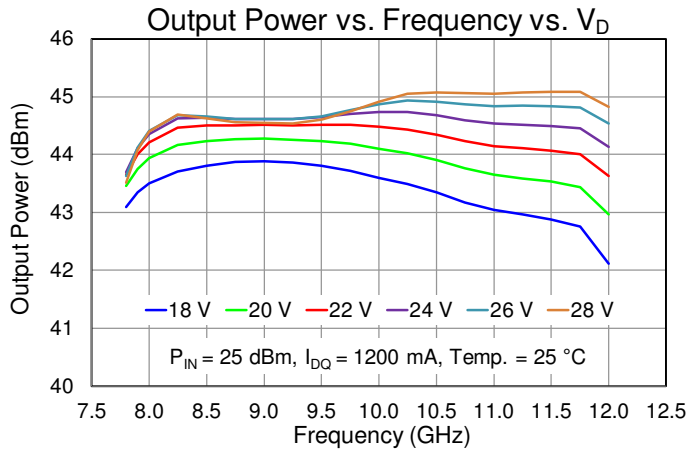
## Performance Plots – Large Signal (Pulsed)



## Performance Plots – Large Signal (CW)

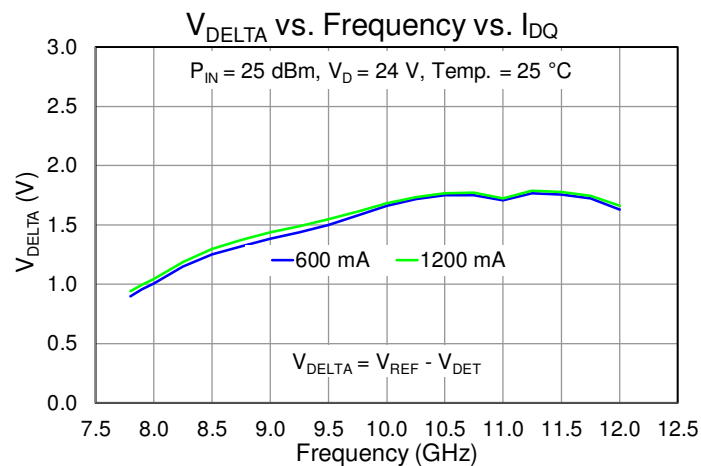
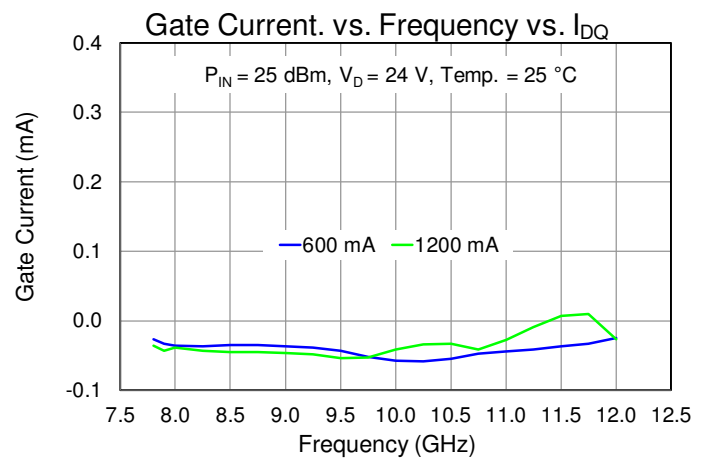
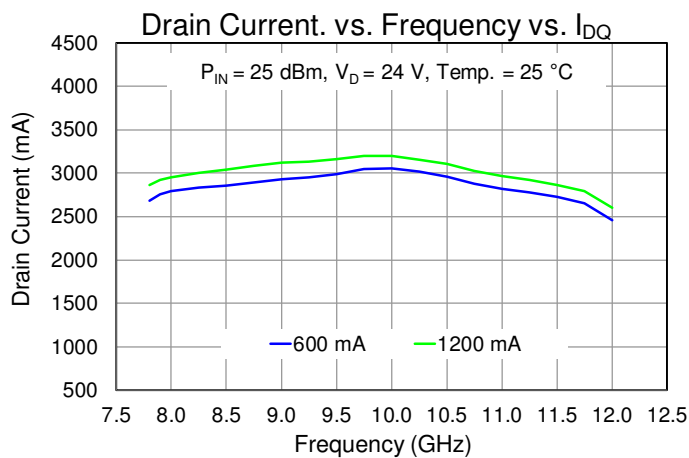
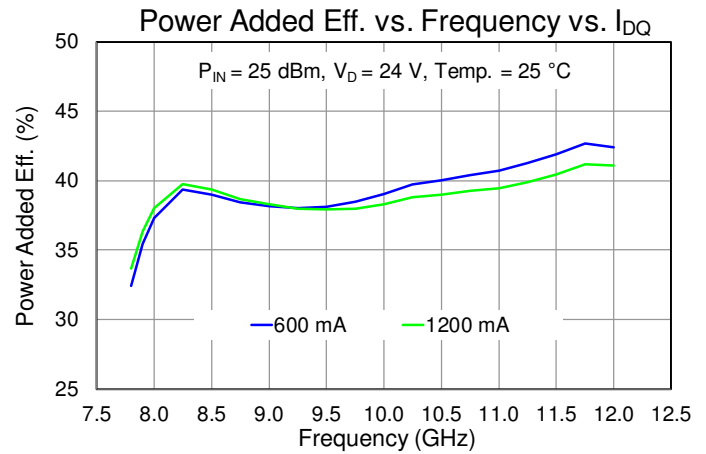
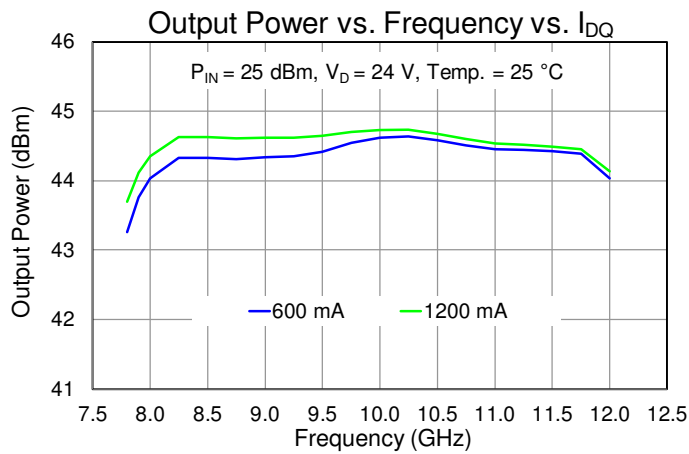


## Performance Plots – Large Signal (CW)

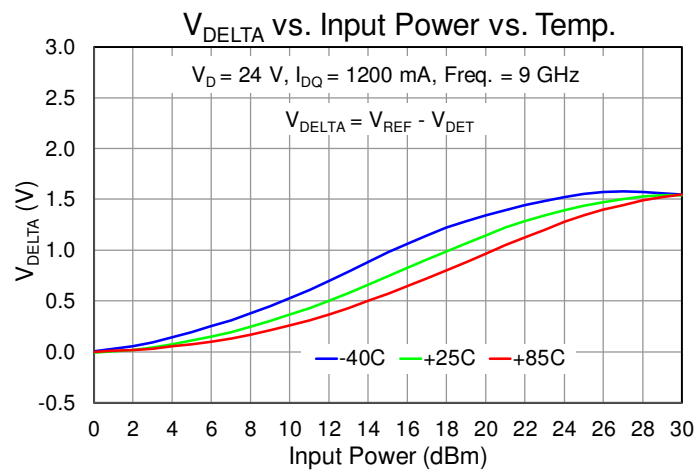
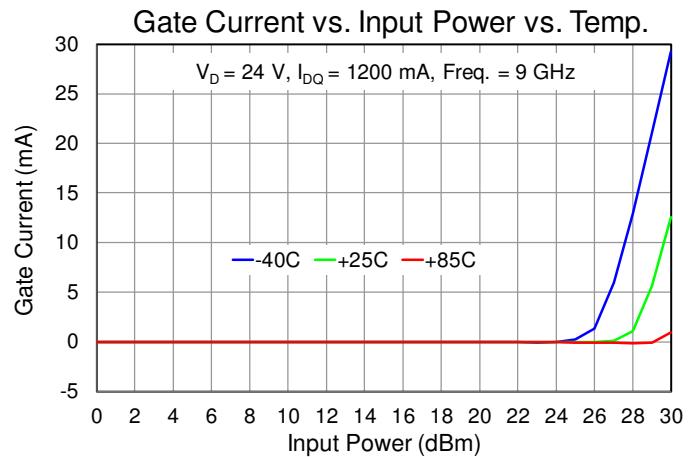
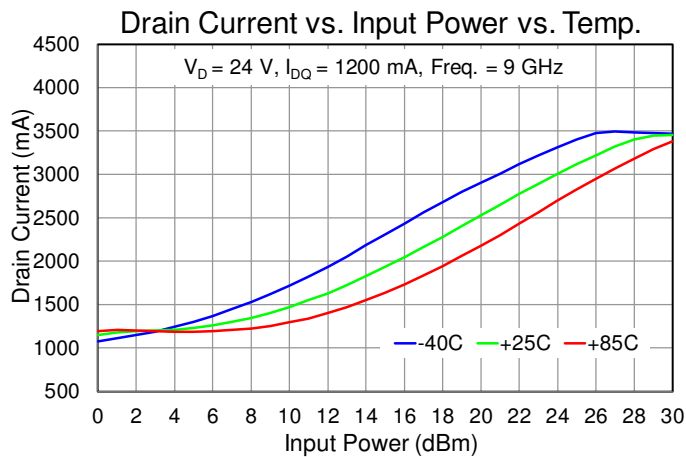
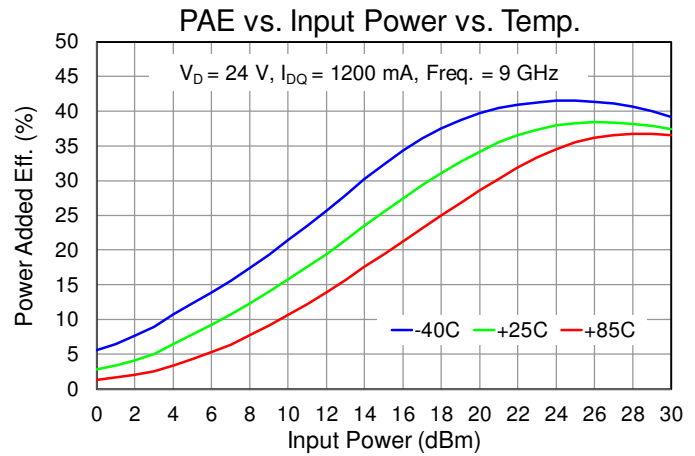
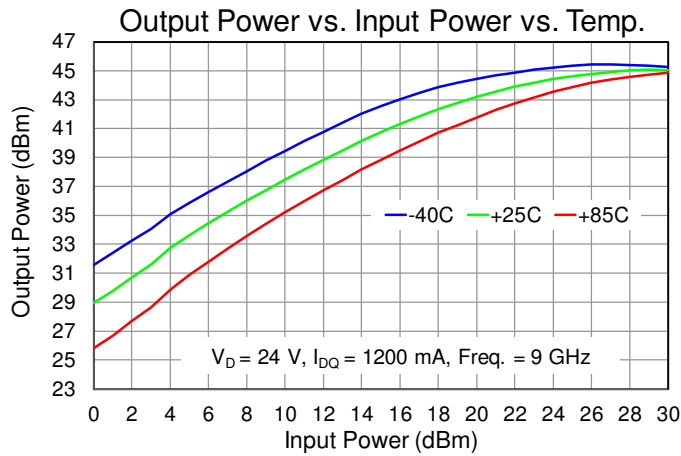




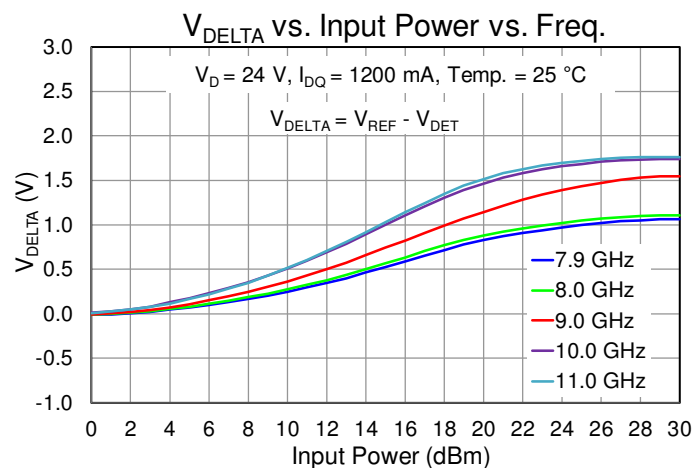
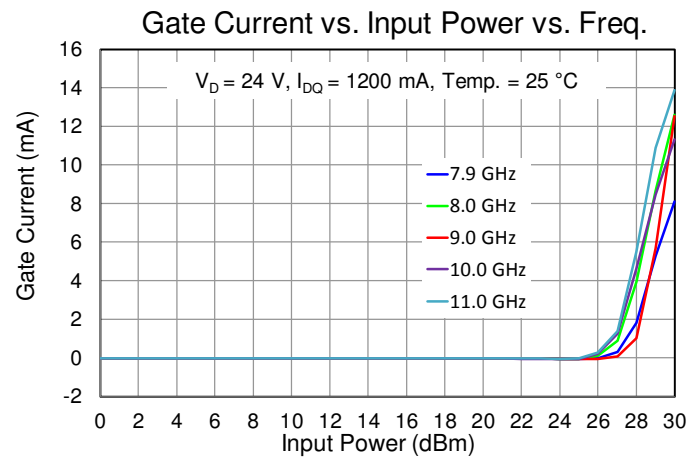
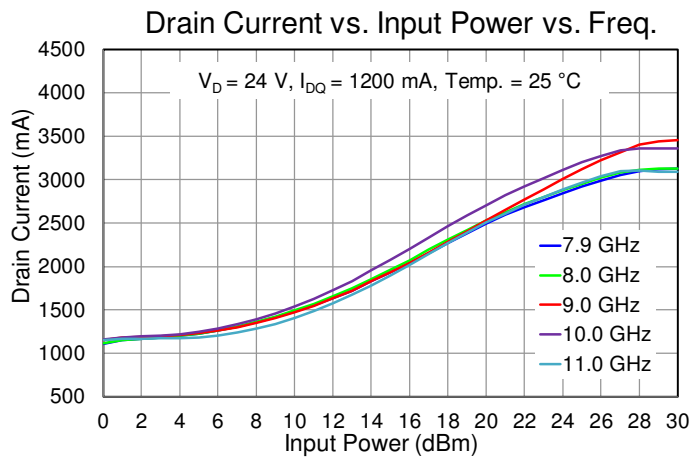
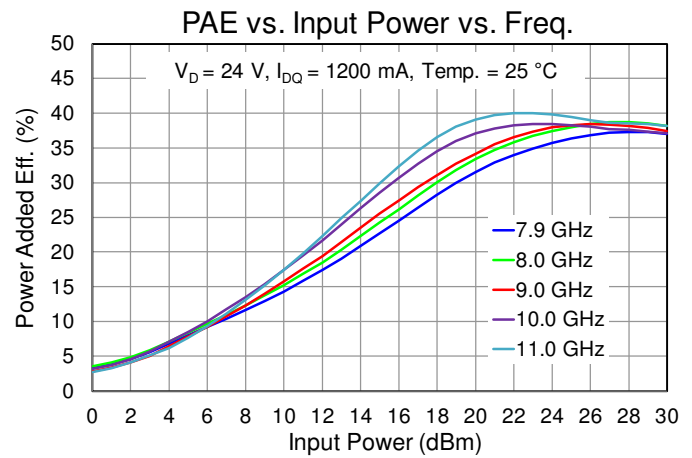
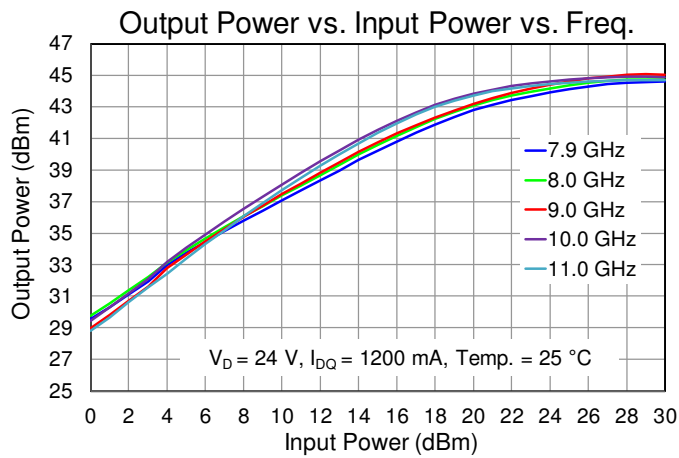
## Performance Plots – Large Signal (CW)



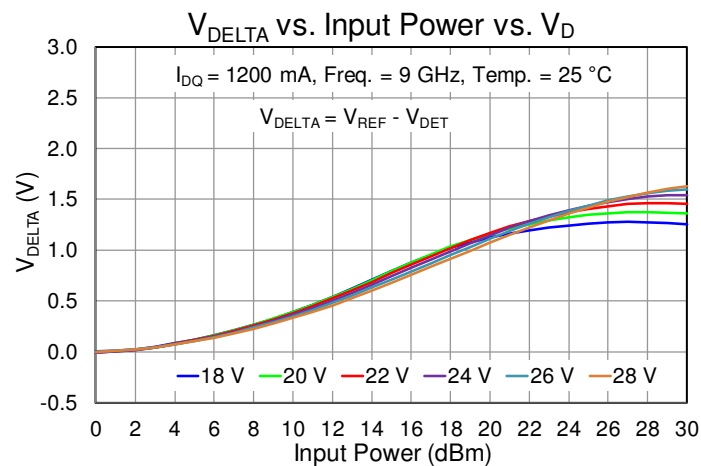
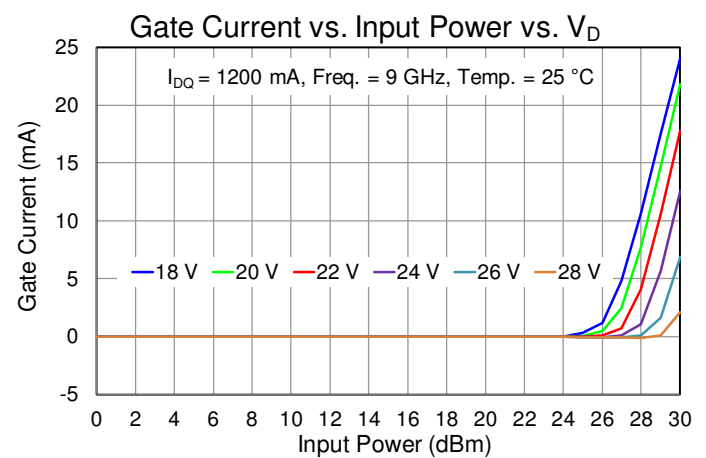
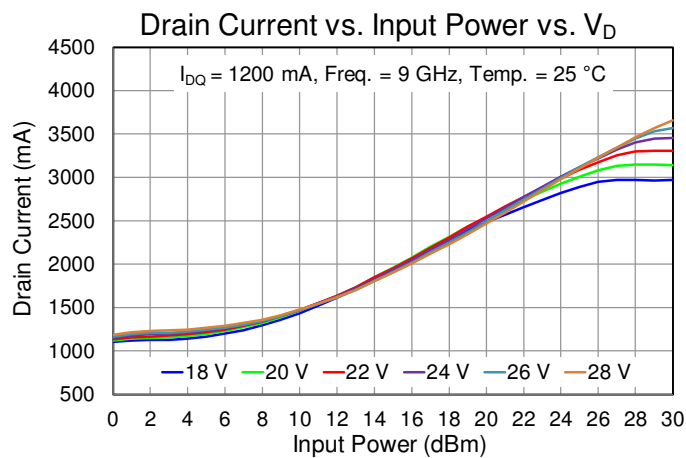
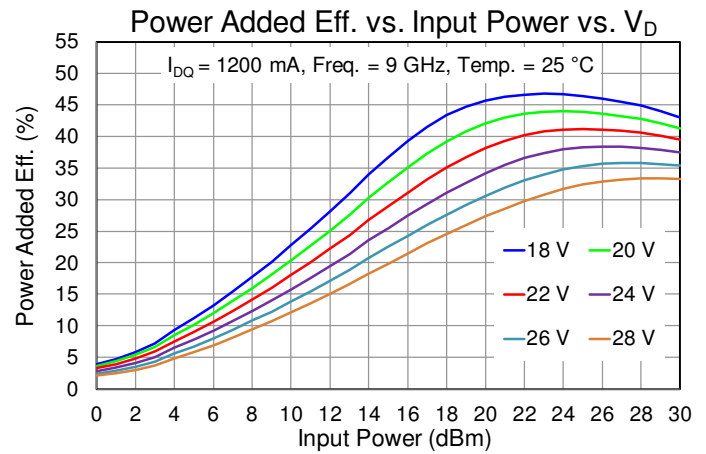
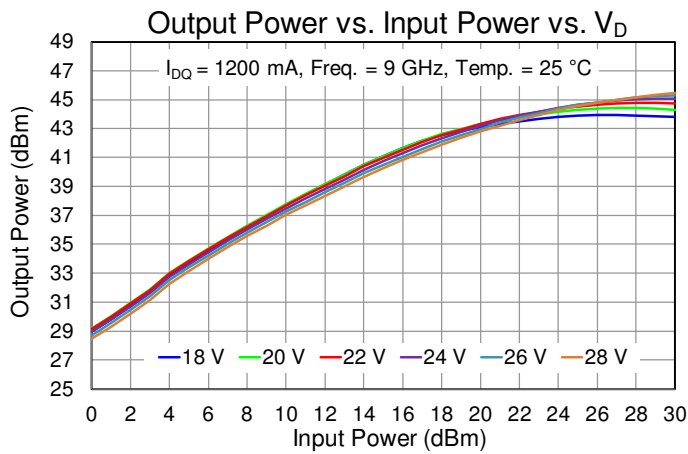
## Performance Plots – Large Signal (CW)



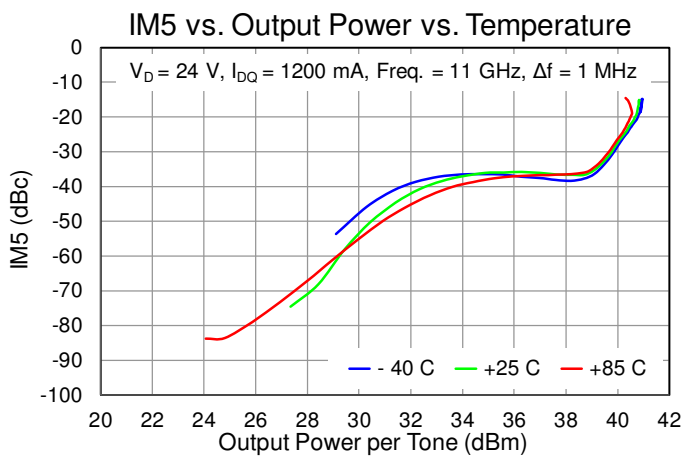
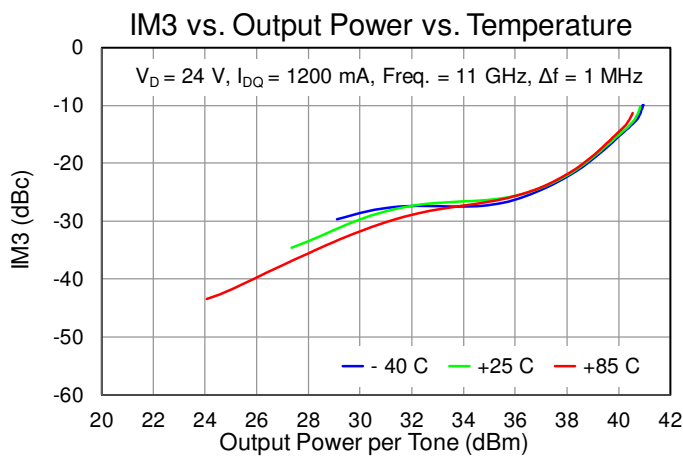
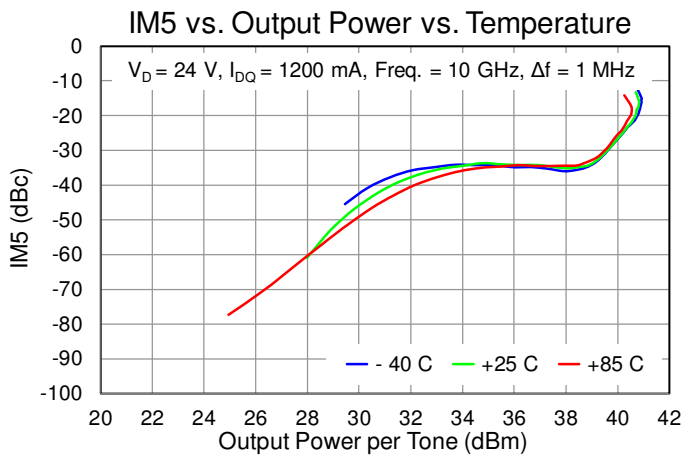
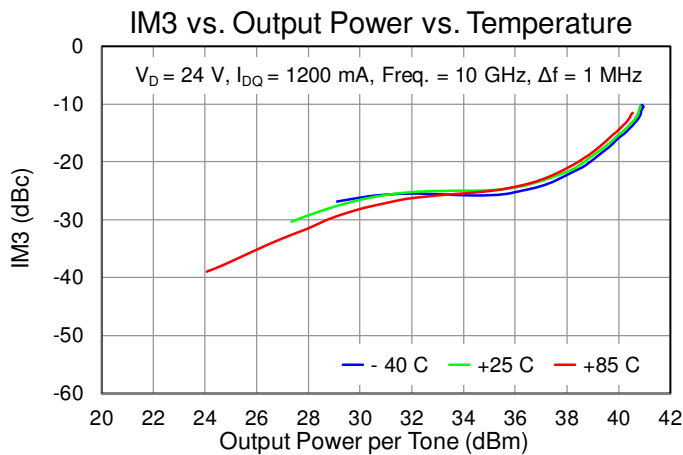
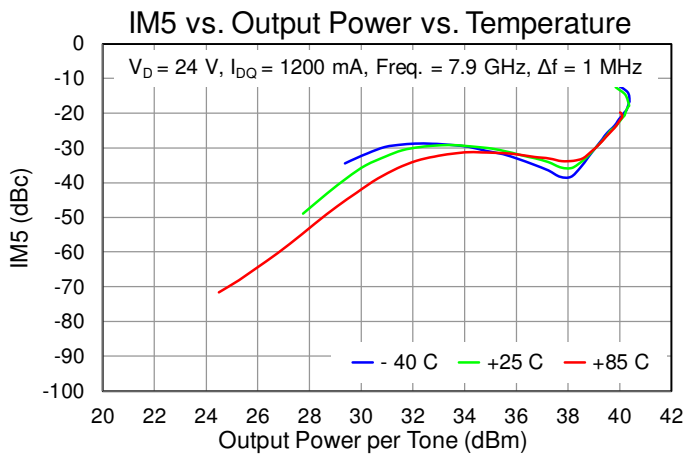
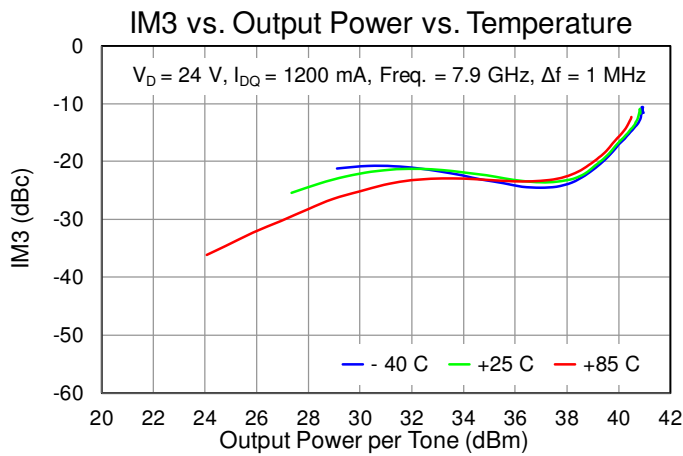
## Performance Plots – Large Signal (CW)



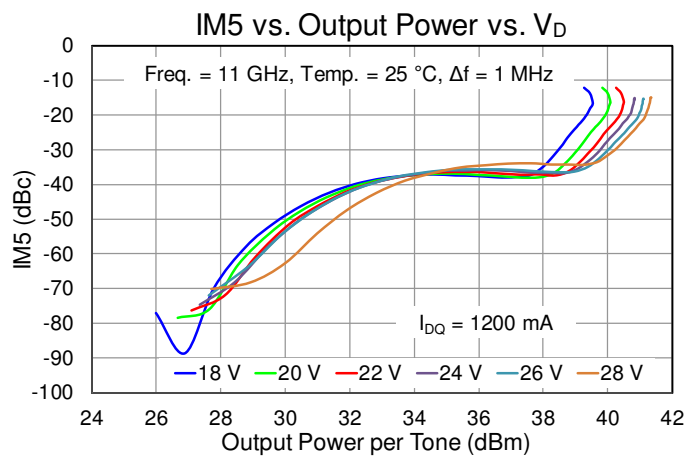
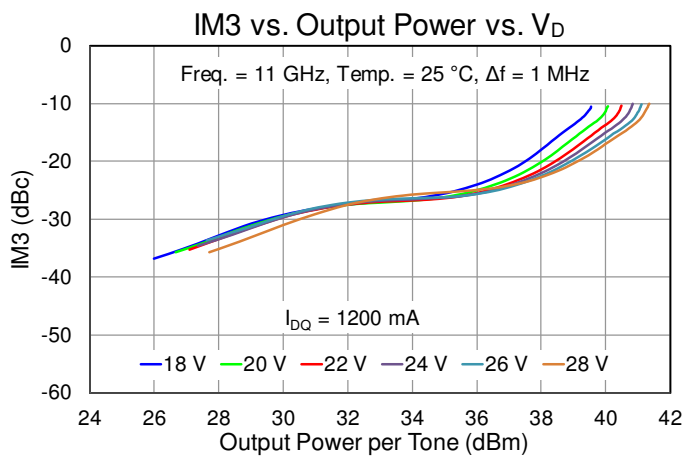
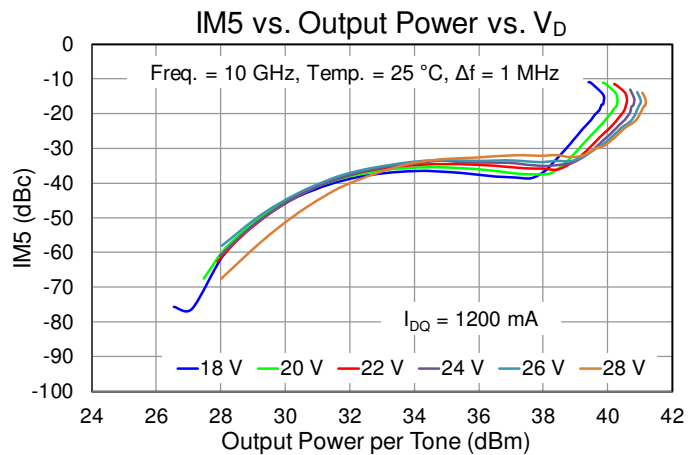
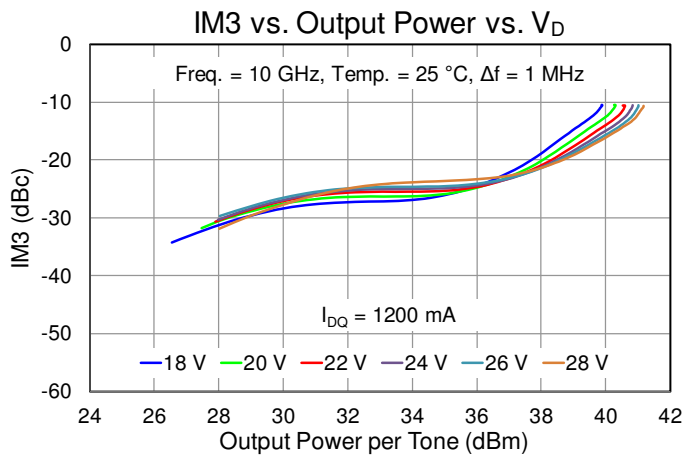
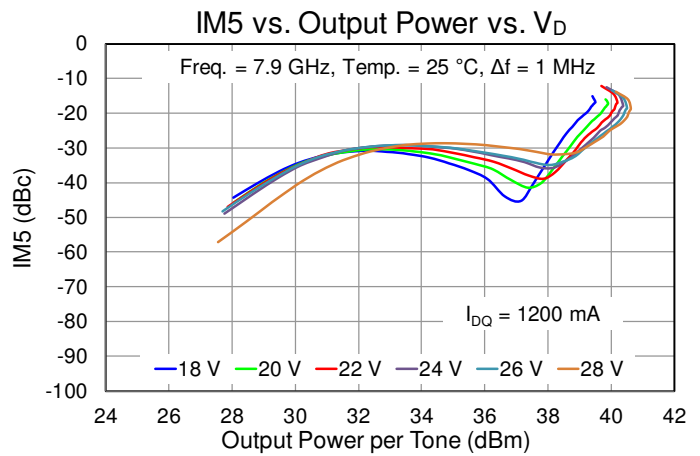
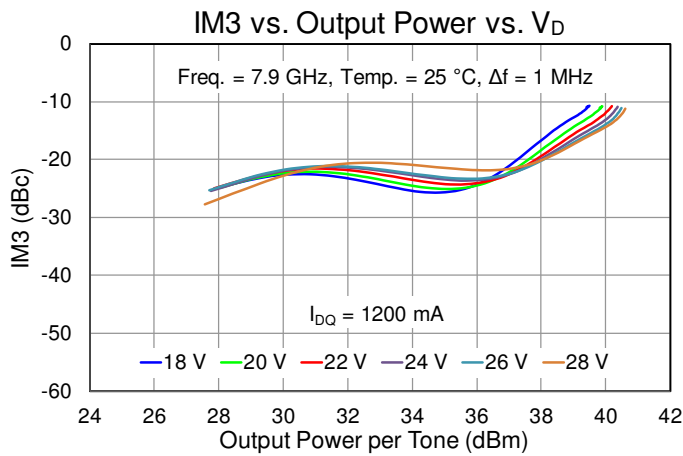
## Performance Plots – Large Signal (CW)



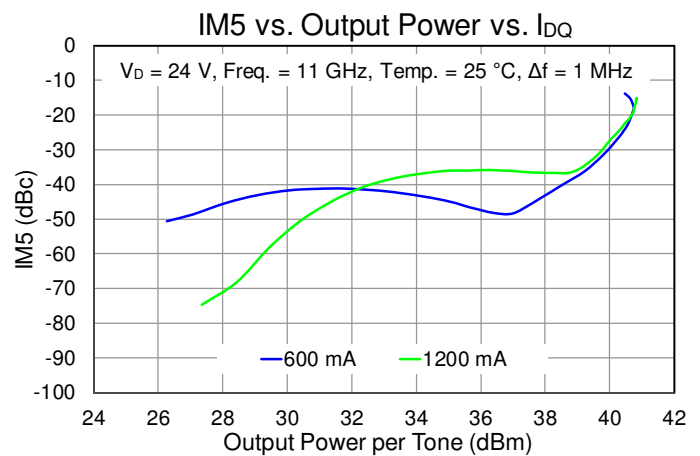
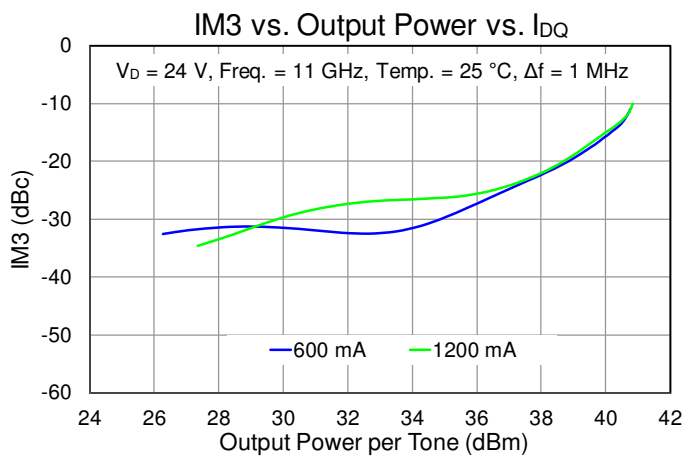
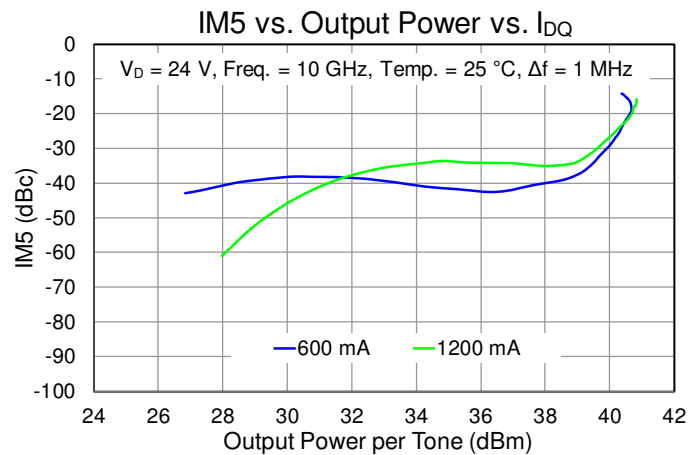
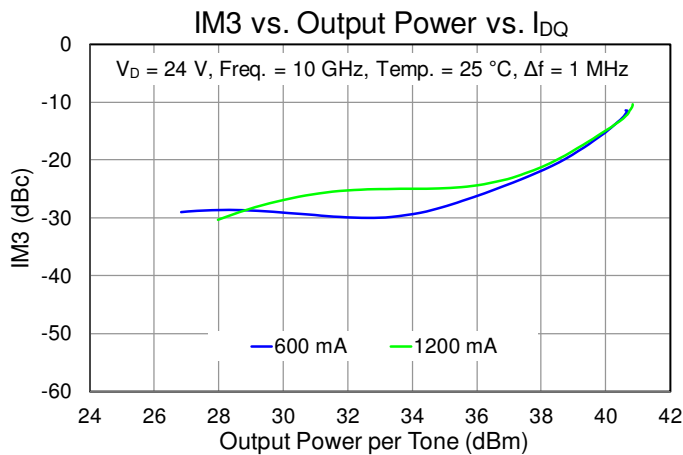
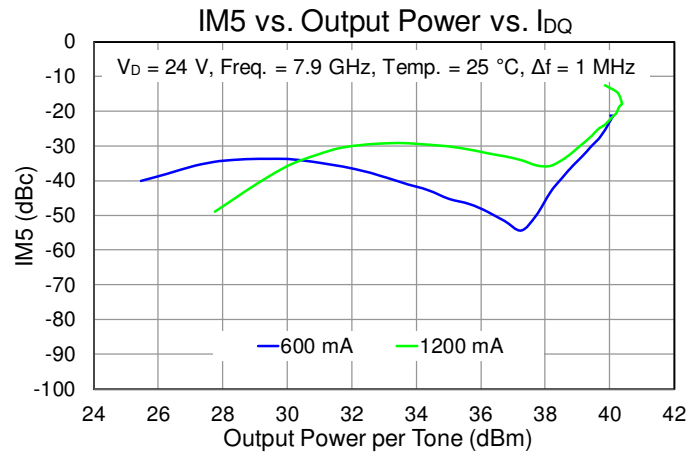
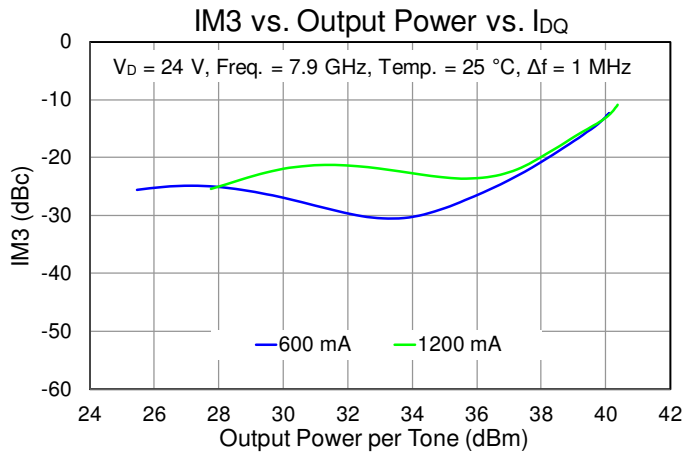
## Performance Plots – Linearity



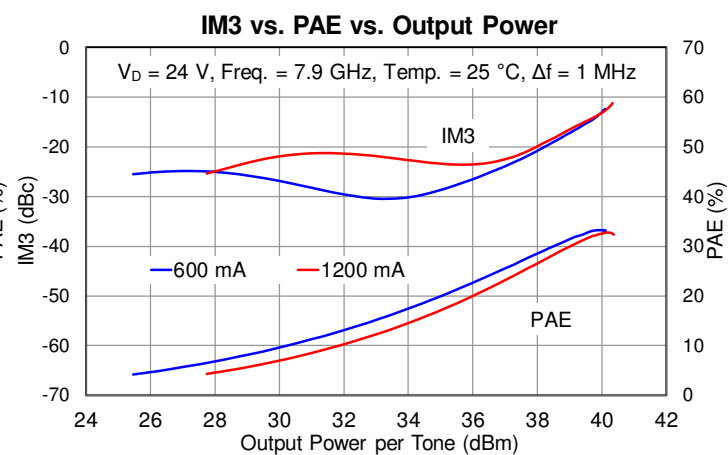
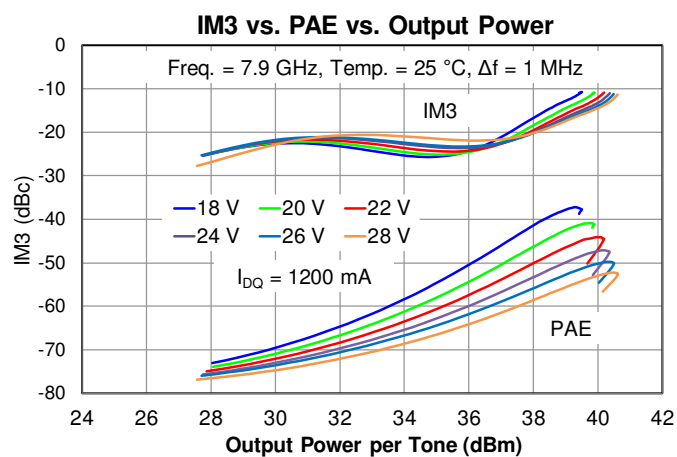
## Performance Plots – Linearity



## Performance Plots – Linearity

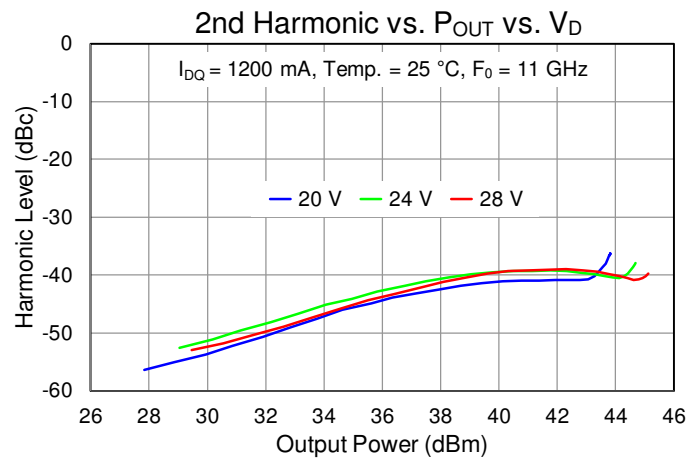
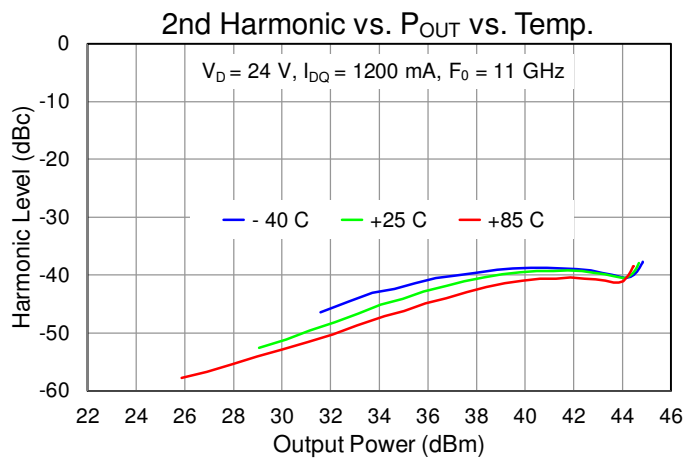
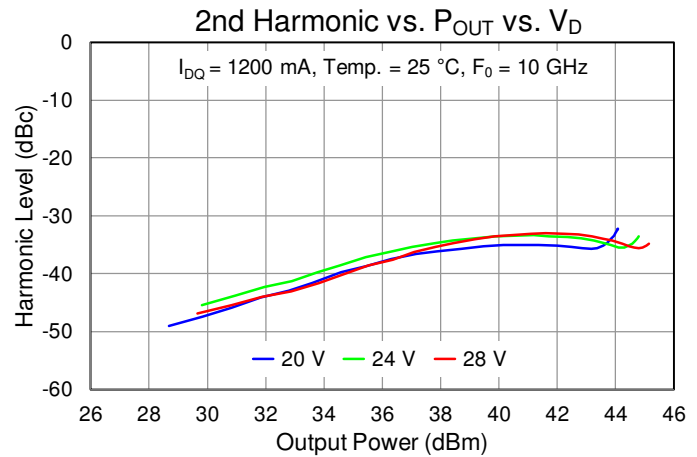
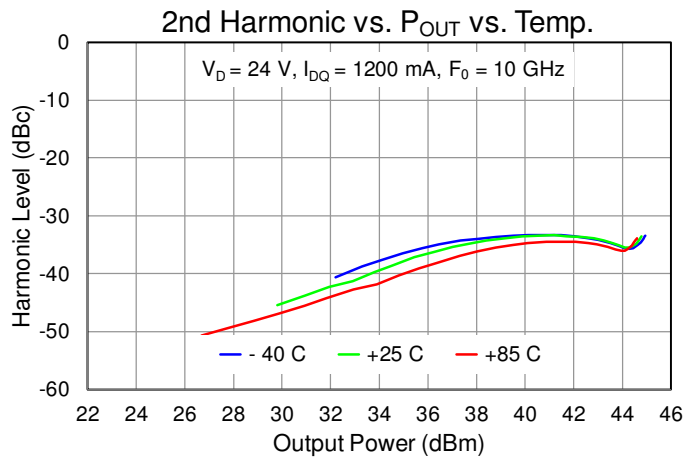
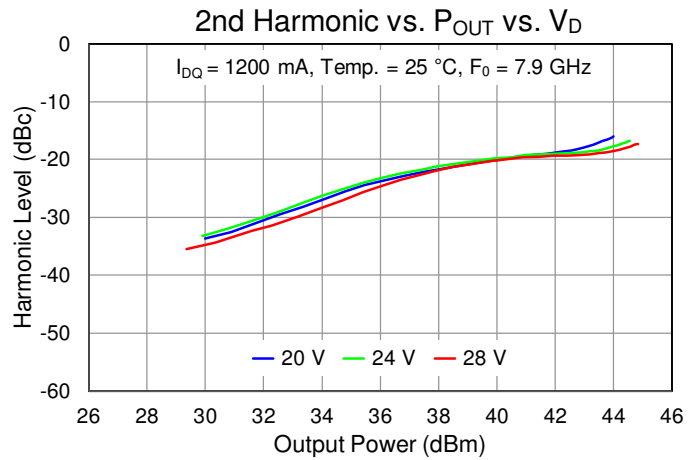
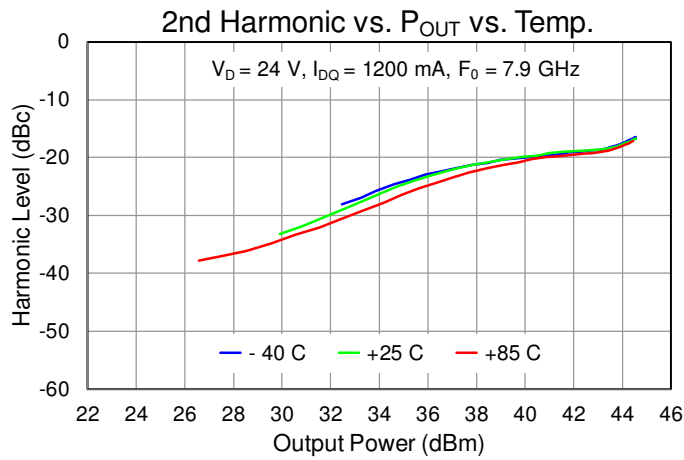


## Performance Plots – Linearity

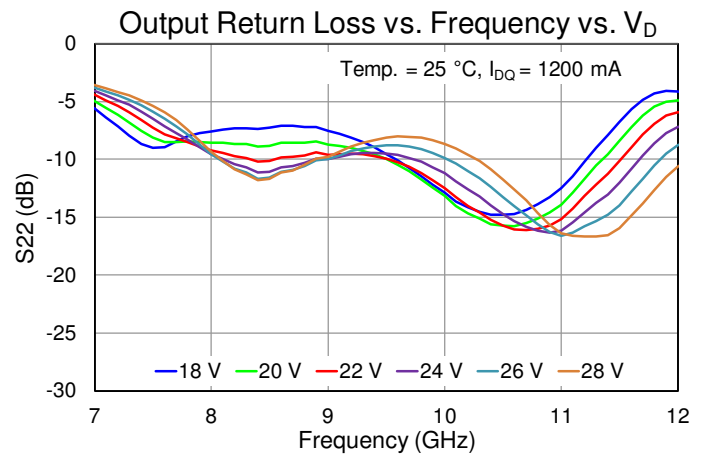
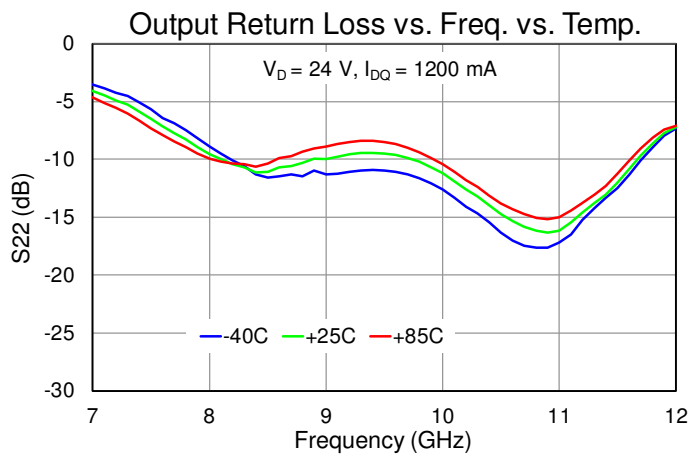
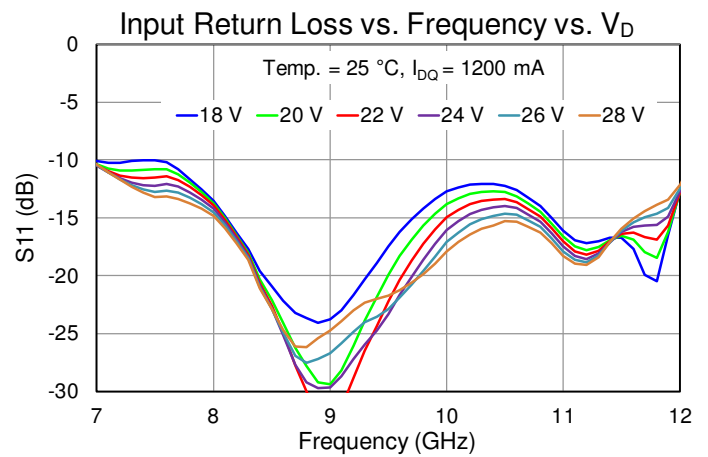
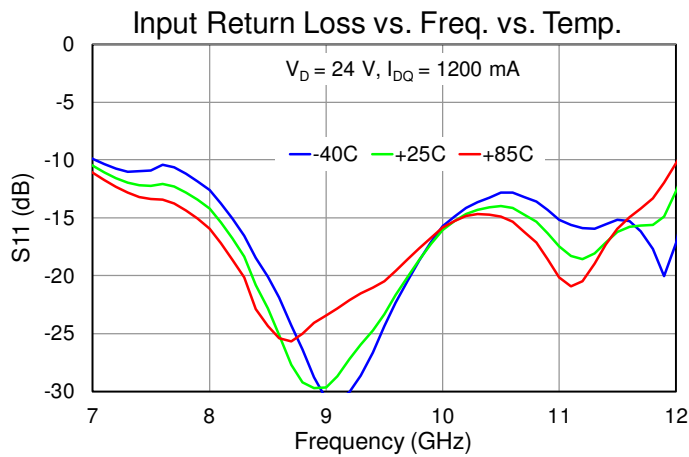
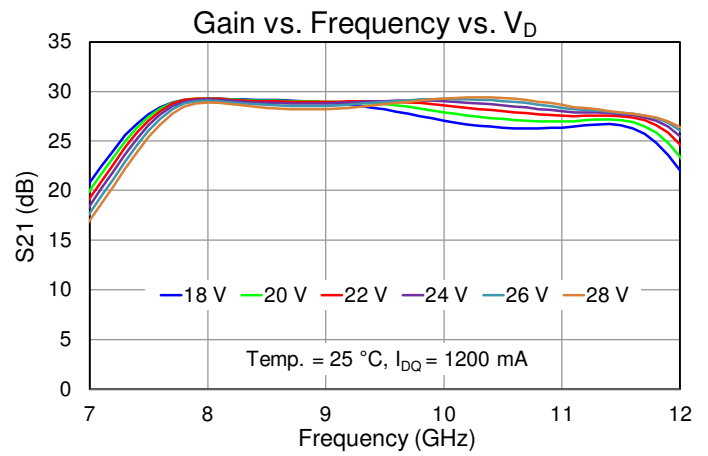
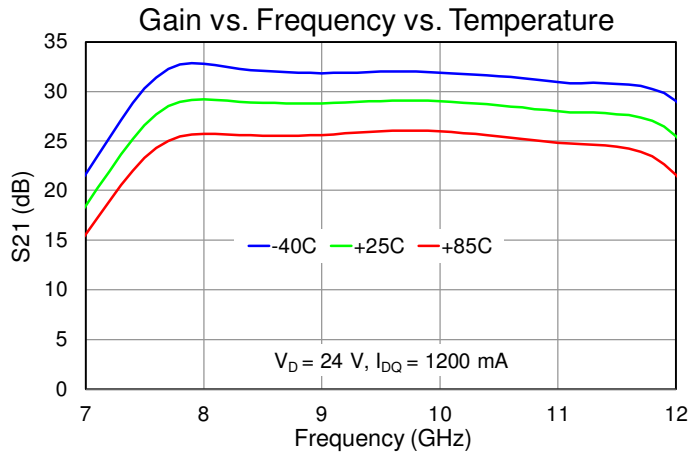




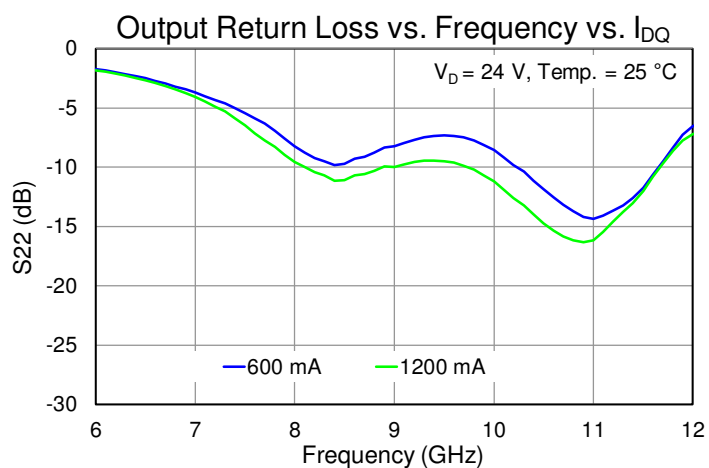
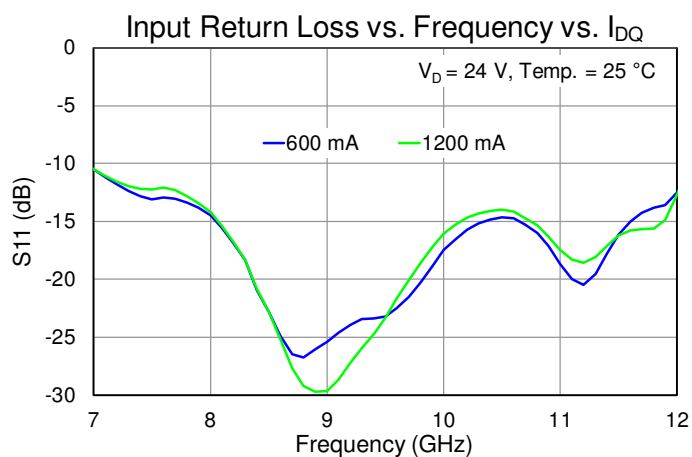
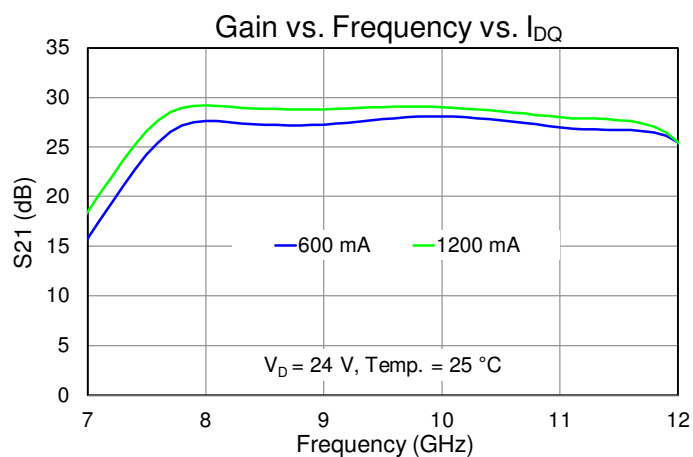
## Performance Plots – Harmonics



Performance Plots – Small Signal



## Performance Plots – Small Signal



## Thermal and Reliability Information

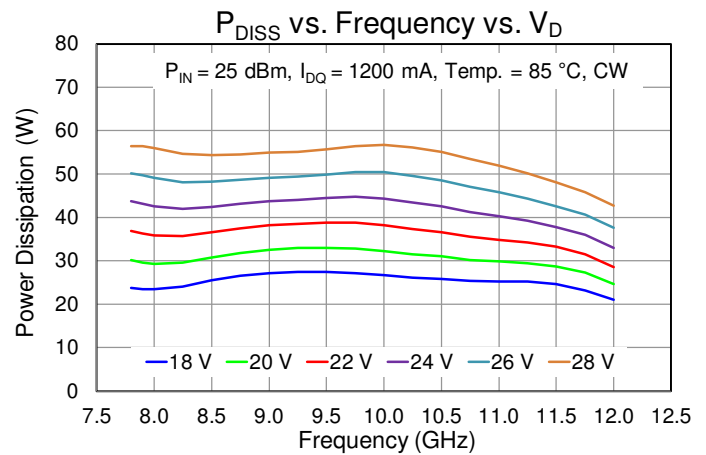
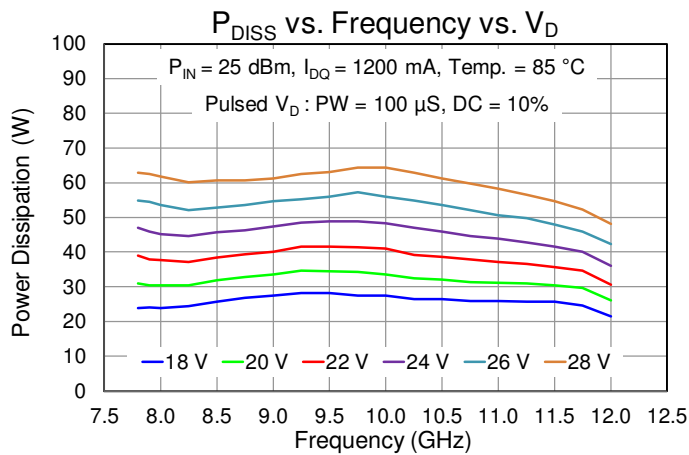
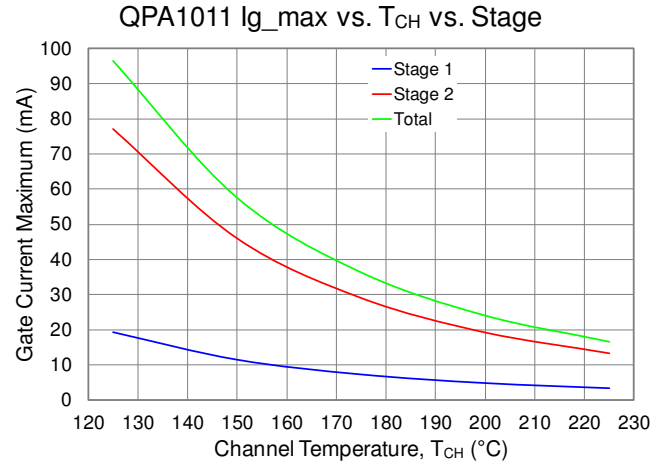
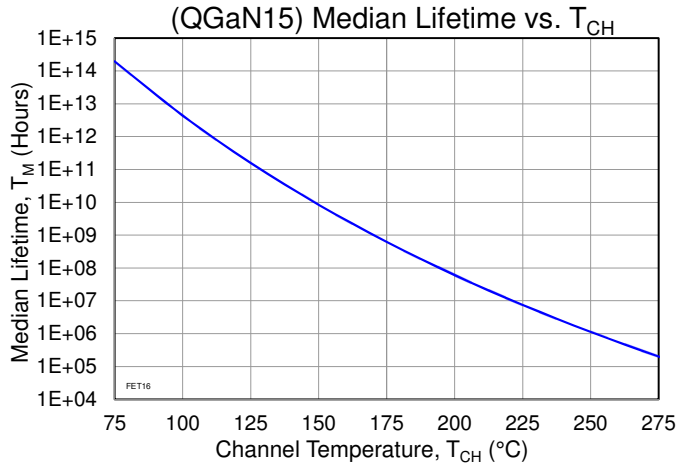
| Parameter                                                 | Test Conditions                                                                                                                                                                                                                                                        | Value    | Units |
|-----------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------|-------|
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +24 V, I <sub>DQ</sub> = 1200 mA,<br>Pulsed V <sub>D</sub> : PW = 100 us; DC = 10%,<br>Freq = 9.75 GHz, P <sub>IN</sub> = 25 dBm, I <sub>D_Drive</sub> = 3.3 A,<br>P <sub>OUT</sub> = 44.7 dBm, P <sub>DISS</sub> = 48.9 W | 1.49     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Under RF drive)   |                                                                                                                                                                                                                                                                        | 158      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 3.6E +09 | Hrs   |
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +24V, I <sub>DQ</sub> = 1200 mA, CW,<br>P <sub>DISS</sub> = 28.8 W                                                                                                                                                         | 2.13     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Quiescent, No RF) |                                                                                                                                                                                                                                                                        | 147      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 1.2E 10  | Hrs   |
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +24 V, I <sub>DQ</sub> = 1200 mA, CW,<br>Freq = 9.75 GHz, P <sub>IN</sub> = 25 dBm, I <sub>D_Drive</sub> = 2.9 A,<br>P <sub>OUT</sub> = 44.2 dBm, P <sub>DISS</sub> = 44.7 W                                               | 2.08     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Under RF drive)   |                                                                                                                                                                                                                                                                        | 178      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 4.7E +08 | Hrs   |
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +20 V, I <sub>DQ</sub> = 1200 mA,<br>Pulsed V <sub>D</sub> : PW = 100 us; DC = 10%,<br>Freq = 9.25 GHz, P <sub>IN</sub> = 25 dBm, I <sub>D_Drive</sub> = 3.0 A,<br>P <sub>OUT</sub> = 44.1 dBm, P <sub>DISS</sub> = 34.6 W | 1.39     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Under RF drive)   |                                                                                                                                                                                                                                                                        | 133      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 6.0E +10 | Hrs   |
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +20V, I <sub>DQ</sub> = 1200 mA, CW,<br>P <sub>DISS</sub> = 24 W                                                                                                                                                           | 2.13     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Quiescent, No RF) |                                                                                                                                                                                                                                                                        | 136      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 4.2E +10 | Hrs   |
| Thermal Resistance ( $\theta_{JC}$ ) <sup>(1)</sup>       | T <sub>BASE</sub> = 85 °C, V <sub>D</sub> = +20 V, I <sub>DQ</sub> = 1200 mA, CW,<br>Freq = 9.5GHz, P <sub>IN</sub> = 25 dBm, I <sub>D_Drive</sub> = 2.8 A,<br>P <sub>OUT</sub> = 43.7 dBm, P <sub>DISS</sub> = 33 W                                                   | 1.94     | °C/W  |
| Channel Temperature (T <sub>CH</sub> ) (Under RF drive)   |                                                                                                                                                                                                                                                                        | 149      | °C    |
| Median Lifetime (T <sub>M</sub> )                         |                                                                                                                                                                                                                                                                        | 9.4E +09 | Hrs   |

### Notes:

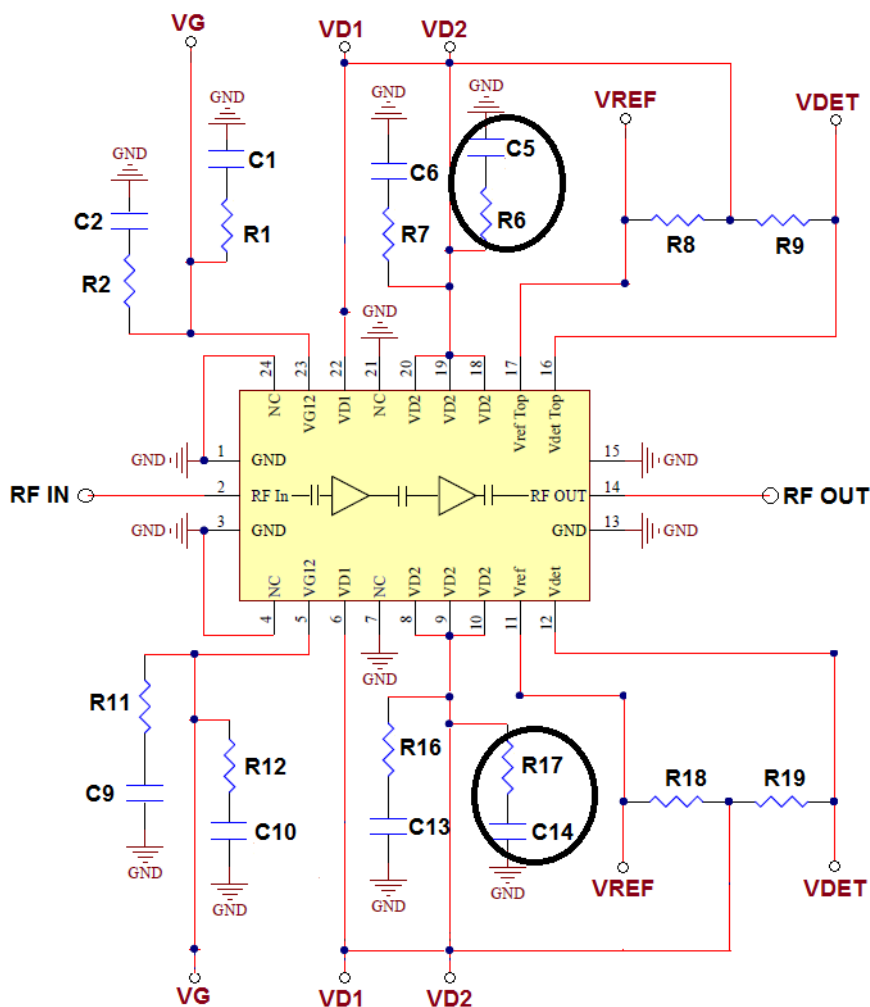
1. Thermal resistance is measured to the package backside.

### Median Lifetime

Median Life Test Conditions:  $V_D = +28\text{ V}$ ; Failure Criteria = 10 % reduction in  $I_{D\_MAX}$  during DC Life Testing



### Applications Circuit for Linear and Pulsed Operations



Note:  $V_{\Delta} = V_{REF} - V_{DET}$

- QPA1011 can be biased from either the top side or bottom side.
- $V_{D1}$  and  $V_{D2}$  need to be tied together
- $V_{D1} / V_{D2}$  and  $V_{REF} / V_{DET}$  have to be on the same side for  $V_{\Delta}$  to work.
- Bypassing components required for the side(s) being biased.
- The extra bias components (R6, R17, C5 and C14) are required for optimum linearity.

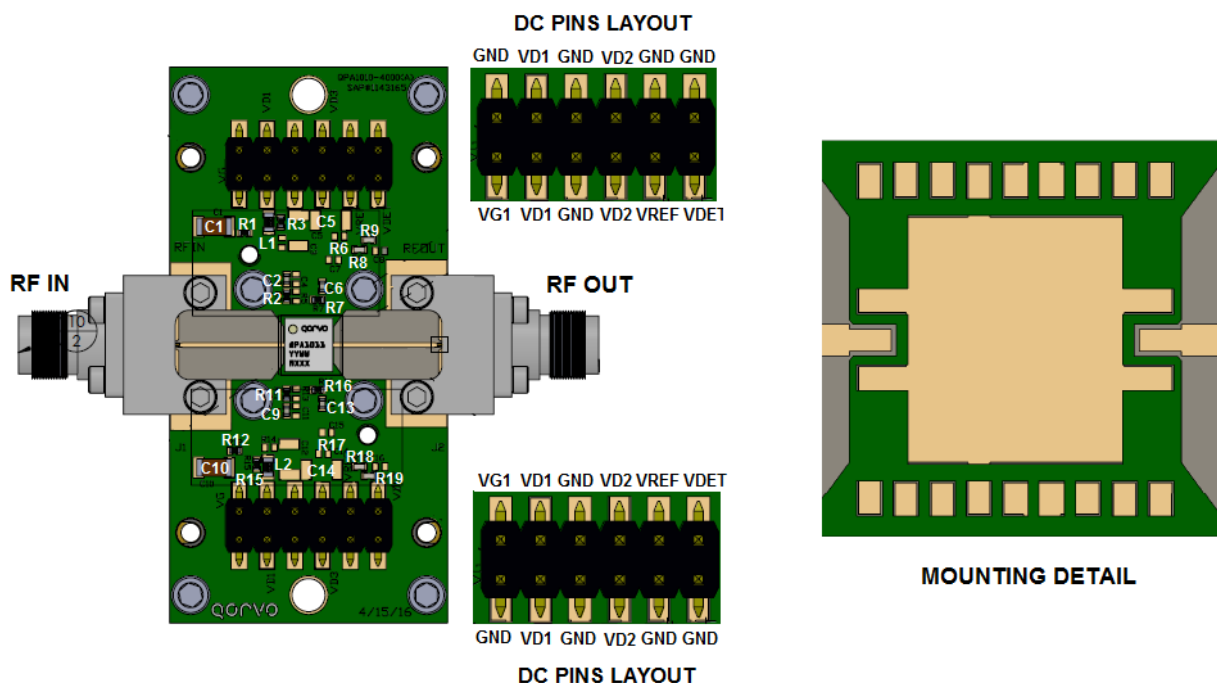
### Bias Up Procedure

1. Set  $I_D$  limit to 4000 mA,  $I_G$  limit to 20 mA
2. Apply  $-5$  V to  $V_G$
3. Apply  $+24$  V to  $V_D$ ; ensure  $I_{DQ}$  is approx. 0 mA
4. Adjust  $V_G$  until  $I_{DQ} = 1200$  mA ( $V_G \sim -1.9$  V Typ.).
5. Turn on RF supply

### Bias Down Procedure

1. Turn off RF supply
2. Reduce  $V_G$  to  $-5$  V; ensure  $I_{DQ}$  is approx. 0 mA
3. Set  $V_D$  to 0 V
4. Turn off  $V_D$  supply
5. Turn off  $V_G$  supply

## Evaluation Board (EVB) Layout Assembly for Pulsed Operation



Note: PCB is a multilayer

1. All 4 metal thicknesses are 0.5 oz
2. Upper core 1 is Rogers 4003C, 8 mil thick
3. Lower core 2 is 370HR, 6 mil thick
4. Pre-Preg is an epoxy coated glass fabric
5. Total finished PCB thickness is 25 ±3 mil
6. This EVB uses a copper-coined PCB for optimum thermal management under high dissipation long pulse and/or CW conditions

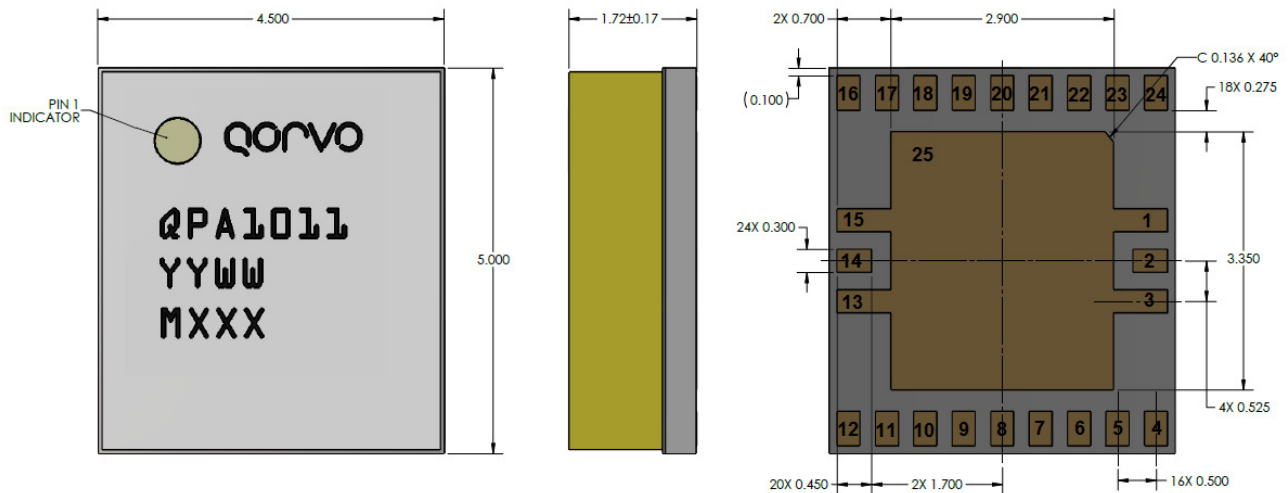
## Bill of Materials for EVB

| Reference Des.                                    | Value      | Description                | Manuf.  | Part Number |
|---------------------------------------------------|------------|----------------------------|---------|-------------|
| C1, C5, C10, C14                                  | 10 uF      | CAP, 1206, 50 V, 20 %, X5R | Various | –           |
| C2, C6, C9, C13                                   | 0.01 uF    | CAP, 0402, 50 V, 10 %, X7R | Various | –           |
| R1, R12                                           | 5.1 Ohm    | RES, 0402, 50V, 5 %, SMT   | Various | –           |
| R2, R3, R6, R7, R11, R15, R16, R17 <sup>(1)</sup> | 0 Ohm      | RES, 0402, 5 %, SMD        | Various | –           |
| R8, R9, R18, R19                                  | 25.5 K Ohm | RES, 0402, 1/16W, 1%, 0402 | Various | –           |
| L1, L2 <sup>(1)</sup>                             | 0 Ohm      | RES, 0603, 1/10 W          | Various | –           |

Note:

1. These components are acting as the jumpers for this EVB.

### Mechanical Information



Units: millimeters

Tolerances: unless specified

x.xx = ± 0.25

x.xxx = ± 0.100

Materials:

Base: Laminate

Lid: FR4

All metalized features are gold plated

Part is epoxy sealed

Marking:

QPA1011: Part number

YY: Part Assembly year

WW: Part Assembly week

MXXX: Batch ID

### Pin Description

| Pad No.              | Symbol            | Description                                                                                                                               |
|----------------------|-------------------|-------------------------------------------------------------------------------------------------------------------------------------------|
| 1, 3, 13, 15, Center | GND               | Ground. Must be grounded on the PCB. Conductive filled vias recommended for least inductance and improved thermal performance             |
| 2                    | RF <sub>IN</sub>  | RF Input; matched to 50 Ω; DC blocked                                                                                                     |
| 4, 7, 21, 24         | N/C               | Not connected internally. Recommended to be grounded                                                                                      |
| 5, 23                | V <sub>G1-2</sub> | Stage 1-2 Gate Voltage. Bias network is required; see recommended Application Information above on page 21                                |
| 6, 22                | V <sub>D1</sub>   | Stage 1 Drain Voltage. Bias network is required; see recommended Application Information above on page 21                                 |
| 8 – 10, 18 - 20      | V <sub>D2</sub>   | Stage 2 Drain voltage; Bias network is required; must be biased from both sides; see recommended Application Information above on page 21 |
| 11, 17               | V <sub>REF</sub>  | Reference voltage                                                                                                                         |
| 12, 16               | V <sub>DET</sub>  | Detector voltage                                                                                                                          |
| 14                   | RF <sub>OUT</sub> | RF Output; matched to 50 Ω; DC blocked                                                                                                    |



### Handling Precautions

| Parameter                        | Rating | Standard                           |
|----------------------------------|--------|------------------------------------|
| ESD – Human Body Model (HBM)     | TBD    | ESDA / JEDEC JS-001-2012           |
| ESD – Charged Device Model (CDM) | TBD    | ESDA / JEDEC JS-002-2014           |
| MSL – Convection Reflow 260 °C   | TBD    | JEDEC standard IPC/JEDEC J-STD-020 |



Caution!  
ESD-Sensitive Device

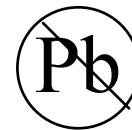
### Solderability

Compatible with the latest version of J-STD-020, Lead-free solder, 260 °C

### RoHS Compliance

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU. This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free
- Qorvo Green



### Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

**Tel:** 1-844-890-8163

**Web:** [www.qorvo.com](http://www.qorvo.com)

**Email:** [customer.support@qorvo.com](mailto:customer.support@qorvo.com)

For technical questions and application information: **Email:** [sjcapapplications.engineering@qorvo.com](mailto:sjcapapplications.engineering@qorvo.com)

### Important Notice

The information contained herein is believed to be reliable; however, Qorvo makes no warranties regarding the information contained herein and assumes no responsibility or liability whatsoever for the use of the information contained herein. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for Qorvo products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information. **THIS INFORMATION DOES NOT CONSTITUTE A WARRANTY WITH RESPECT TO THE PRODUCTS DESCRIBED HEREIN, AND QORVO HEREBY DISCLAIMS ANY AND ALL WARRANTIES WITH RESPECT TO SUCH PRODUCTS WHETHER EXPRESS OR IMPLIED BY LAW, COURSE OF DEALING, COURSE OF PERFORMANCE, USAGE OF TRADE OR OTHERWISE, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE.**

Without limiting the generality of the foregoing, Qorvo products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.

Copyright 2016 © Qorvo, Inc. | Qorvo is a registered trademark of Qorvo, Inc.



**Стандарт  
Электрон  
Связь**

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

**Наши контакты:**

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литера Н,  
помещение 100-Н Офис 331